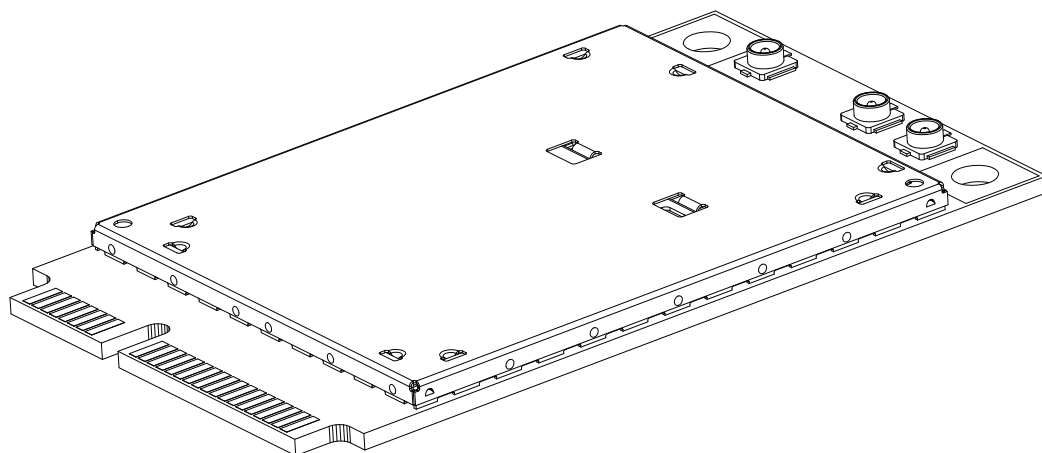




# Product Technical Specification & Customer Design Guidelines

## AirPrime MC7330



**SIERRA**  
WIRELESS®

4114225

Rev 10

Proprietary and Confidential  
Contents subject to change



## Important Notice

Due to the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless accepts no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

## Safety and Hazards

Do not operate the Sierra Wireless modem in areas where blasting is in progress, where explosive atmospheres may be present, near medical equipment, near life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the Sierra Wireless modem **MUST BE POWERED OFF**. The Sierra Wireless modem can transmit signals that could interfere with this equipment.

Do not operate the Sierra Wireless modem in any aircraft, whether the aircraft is on the ground or in flight. In aircraft, the Sierra Wireless modem **MUST BE POWERED OFF**. When operating, the Sierra Wireless modem can transmit signals that could interfere with various onboard systems.

---

*Note: Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. Sierra Wireless modems may be used at this time.*

---

The driver or operator of any vehicle should not operate the Sierra Wireless modem while in control of a vehicle. Doing so will detract from the driver or operator's control and operation of that vehicle. In some states and provinces, operating such communications devices while in control of a vehicle is an offence.

## Limitation of Liability

The information in this manual is subject to change without notice and does not represent a commitment on the part of Sierra Wireless. SIERRA WIRELESS AND ITS AFFILIATES SPECIFICALLY DISCLAIM LIABILITY FOR ANY AND ALL DIRECT, INDIRECT, SPECIAL, GENERAL, INCIDENTAL, CONSEQUENTIAL, PUNITIVE OR EXEMPLARY DAMAGES INCLUDING, BUT NOT LIMITED TO, LOSS OF PROFITS OR REVENUE OR ANTICIPATED PROFITS OR REVENUE ARISING OUT OF THE USE OR INABILITY TO USE ANY SIERRA WIRELESS PRODUCT, EVEN IF SIERRA WIRELESS AND/OR ITS AFFILIATES HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES OR THEY ARE FORESEEABLE OR FOR CLAIMS BY ANY THIRD PARTY.

Notwithstanding the foregoing, in no event shall Sierra Wireless and/or its affiliates aggregate liability arising under or in connection with the Sierra Wireless product, regardless of the number of events, occurrences, or claims giving rise to liability, be in excess of the price paid by the purchaser for the Sierra Wireless product.

## Patents

This product may contain technology developed by or for Sierra Wireless Inc.

This product includes technology licensed from QUALCOMM®.

This product is manufactured or sold by Sierra Wireless Inc. or its affiliates under one or more patents licensed from InterDigital Group and MMP Portfolio Licensing.

## Copyright

©2015 Sierra Wireless. All rights reserved.

## Trademarks

Sierra Wireless®, AirPrime®, Skylight™, and the Sierra Wireless logo are trademarks of Sierra Wireless.

Watcher™ is a registered trademark of NETGEAR, Inc., used under license.

Windows® is a registered trademark of Microsoft Corporation.

QUALCOMM® is a registered trademark of QUALCOMM Incorporated. Used under license.

Other trademarks are the property of their respective owners.

## Contact Information

Sales Desk:	Phone:	1-604-232-1488
	Hours:	8:00 AM to 5:00 PM Pacific Time
	E-mail:	sales@sierrawireless.com
Post:	Sierra Wireless 13811 Wireless Way Richmond, BC Canada V6V 3A4	
Fax:	1-604-231-1109	
Web:	www.sierrawireless.com	

Consult our website for up-to-date product descriptions, documentation, application notes, [firmware](#) upgrades, troubleshooting tips, and press releases:

[www.sierrawireless.com](http://www.sierrawireless.com)

## Revision History

Revision number	Release date	Changes
1	April 2013	Initial release.
2	June 2013	Added Class B temperature info
3	September 2013	Updated Introduction, Electrical, RF, Power, and Regulatory content, plus general refresh.

Revision number	Release date	Changes
4	September 2013	Updated operating temperature details, added DC bias on GNSS connector, removed GPS_DISABLE_N, updated pins 11,30,32,33,45,47,49,51, added SYSTEM_RESET_N detail and PCM/I2S Audio Interface detail.
5	September 2013	Introduction wording. Updated humidity spec.
6	April 2014	Updated voltage levels and/or pin type (WAKE_N, USIM_DATA, WAN_LED_N), current consumption, ANT_CTRL/GPIO and GPIO/DPR pin definitions. Added note indicating voice support is SKU-specific. Temperature spec wording changes.
7	April 2014	Minor formatting fixes
8	June 2014	Updated temperature specification details in <a href="#">Table 7-1 on page 61</a> . Updated GSM, UMTS and LTE Rx frequency details in Testing chapter.
9	September 2014	Updated temperature spec details in <a href="#">Table 7-1 on page 61</a> .
10	March 2015	Updated <a href="#">Table 4-9 on page 48</a> (# of satellites)





# Contents

<b>Introduction</b>	<b>15</b>
Supported RF bands	15
Physical features	15
Application interface features	16
Modem features	17
LTE features	17
Short Message Service (SMS) features	18
Position location (GNSS)	18
Warranty and support	18
Supporting documents	18
Accessories	19
Required connectors	19
Ordering information	19
Integration requirements	20
 <b>Standards Compliance</b>	 <b>21</b>
 <b>Electrical Specifications</b>	 <b>23</b>
Host interface pin assignments	25
Power supply	30
USB interface	30
USB high/full speed throughput performance	31
User-developed drivers	31
SIM interface	31
SIM implementation	33

Control interface (Signals) . . . . .	34
WAKE_N — Wake host . . . . .	34
W_DISABLE_N — Wireless disable . . . . .	35
WAN_LED_N—LED output . . . . .	35
SYSTEM_RESET_N—Reset Input . . . . .	36
PCM/I2S Audio Interface . . . . .	36
Antenna control . . . . .	39
<b>RF Specifications . . . . .</b>	<b>41</b>
RF connections . . . . .	41
Shielding . . . . .	41
Antenna and cabling . . . . .	42
Ground connection . . . . .	43
Interference and sensitivity . . . . .	43
Interference from other wireless devices . . . . .	43
Host-generated RF interference . . . . .	43
Device-generated RF interference . . . . .	44
Methods to mitigate decreased Rx performance . . . . .	44
Radiated sensitivity measurement. . . . .	44
Sierra Wireless' sensitivity testing and desensitization investigation . . .	44
Sensitivity vs. frequency . . . . .	45
Supported frequencies. . . . .	45
Conducted Rx sensitivity / Tx power . . . . .	46
GNSS specifications . . . . .	48
<b>Power . . . . .</b>	<b>51</b>
Power consumption . . . . .	51
Module power states . . . . .	53
Power state transitions . . . . .	54



---

Power interface . . . . .	55
Power ramp-up . . . . .	55
Power-up timing . . . . .	55
Transmit power waveform (GSM) . . . . .	56
Power supply noise . . . . .	57
SED (Smart Error Detection) . . . . .	57
Tx power control . . . . .	57
<b>Software Interface . . . . .</b>	<b>59</b>
Support tools . . . . .	59
USB interface . . . . .	59
<b>Mechanical and Environmental Specifications . . . . .</b>	<b>61</b>
Device views . . . . .	62
Labeling . . . . .	63
Electrostatic discharge (ESD) . . . . .	64
Thermal considerations . . . . .	64
<b>Regulatory Compliance and Industry Certifications . . . . .</b>	<b>67</b>
Important notice . . . . .	67
Safety and hazards . . . . .	67
<b>Antenna Specification . . . . .</b>	<b>69</b>
Recommended GNSS antenna specifications . . . . .	71
Antenna tests . . . . .	71
<b>Design Checklist . . . . .</b>	<b>73</b>
<b>Testing . . . . .</b>	<b>75</b>
AT command entry timing requirement . . . . .	75
Acceptance testing . . . . .	75
Acceptance test requirements . . . . .	76
Acceptance test procedure . . . . .	76

Certification testing . . . . .	76
Production testing . . . . .	77
Functional production test . . . . .	77
Production test procedure . . . . .	78
UMTS (WCDMA/GSM) RF transmission path test . . . . .	80
UMTS (WCDMA/GSM) RF receive path test . . . . .	82
LTE RF receive path test . . . . .	84
GNSS RF receive path test . . . . .	86
Quality assurance testing . . . . .	86
Suggested testing equipment . . . . .	87
Testing assistance provided by Sierra Wireless . . . . .	87
IOT/Operator testing . . . . .	87
Extended AT commands for testing. . . . .	88
<b>Packaging . . . . .</b>	<b>91</b>
<b>References . . . . .</b>	<b>93</b>
Sierra Wireless documents . . . . .	93
Command documents . . . . .	93
Other Sierra documents . . . . .	93
Industry/other documents . . . . .	93
<b>Technology Overview . . . . .</b>	<b>95</b>
LTE . . . . .	95
UMTS. . . . .	95
HSPA. . . . .	96
HSPA+. . . . .	96
DC-HSPA+ . . . . .	96
GPRS / EGPRS. . . . .	96
<b>Acronyms . . . . .</b>	<b>99</b>

## List of Tables

Table 1-1: Supported RF bands . . . . .	15
Table 1-2: Modem features . . . . .	17
Table 1-3: Required host-module connectors . . . . .	19
Table 2-1: Standards compliance . . . . .	21
Table 3-1: Connector pin assignments . . . . .	26
Table 3-2: Power and ground specifications . . . . .	30
Table 3-3: USB interface . . . . .	30
Table 3-4: SIM interface signal . . . . .	31
Table 3-5: Module control signals . . . . .	34
Table 3-6: PCM/I2S Interface signals . . . . .	36
Table 3-7: PCM Timing . . . . .	37
Table 3-8: I2S master transmitter timing, . . . . .	38
Table 3-9: Antenna control signals . . . . .	39
Table 4-1: LTE frequency band support . . . . .	45
Table 4-2: LTE bandwidth support. . . . .	45
Table 4-5: Conducted Rx (Receive) sensitivity—LTE bands . . . . .	46
Table 4-3: WCDMA frequency band support. . . . .	46
Table 4-4: GSM frequency band support. . . . .	46
Table 4-6: Conducted Rx (Receive) sensitivity—UMTS bands. . . . .	47
Table 4-7: Conducted Rx (Receive) sensitivity—GSM/EDGE bands. . . . .	47
Table 4-8: Conducted Tx (Transmit) power tolerances . . . . .	47
Table 4-9: GNSS specifications. . . . .	48
Table 5-1: Averaged standby DC power consumption . . . . .	51
Table 5-2: Averaged call mode DC power consumption . . . . .	52
Table 5-3: Miscellaneous DC power consumption . . . . .	53
Table 5-4: Module power states . . . . .	53
Table 5-5: Power state transitions (including voltage/temperature trigger levels). . . . .	54

Table 5-6: Power-on timing parameters (double enumeration) . . . . .	56
Table 5-7: Power-on timing parameters (single enumeration) . . . . .	56
Table 5-8: Dynamic power control of SAR backoff state. . . . .	57
Table 7-1: Mechanical and environmental specifications . . . . .	61
Table A-1: Antenna requirements . . . . .	69
Table A-2: GNSS standalone antenna requirements . . . . .	71
Table B-1: Hardware integration design considerations . . . . .	73
Table C-1: Test settings—UMTS transmission path . . . . .	80
Table C-2: Test settings—UMTS receive path. . . . .	82
Table C-3: Test settings—LTE receive path. . . . .	84
Table C-4: Extended AT commands. . . . .	88
Table F-1: EGPRS power backoff. . . . .	97
Table G-1: Acronyms and definitions . . . . .	99

## List of Figures

Figure 3-1: System block diagram . . . . .	24
Figure 3-2: Expanded RF block diagram . . . . .	25
Figure 3-3: SIM application interface . . . . .	32
Figure 3-4: SIM card contacts (contact view) . . . . .	32
Figure 3-5: Recommended WAKE_N connection . . . . .	34
Figure 3-6: Recommended wireless disable connection . . . . .	35
Figure 3-7: Example LED . . . . .	36
Figure 3-8: PCM_SYNC timing . . . . .	37
Figure 3-9: Timing—PCM_CODEC to Module . . . . .	37
Figure 3-10: Timing—Module to PCM_CODEC . . . . .	37
Figure 3-11: I2S transmitter timing . . . . .	38
Figure 4-1: Module connectors . . . . .	41
Figure 5-1: Voltage/temperature monitoring state machines . . . . .	55
Figure 5-2: Signal timing (Power-on, and USB enumeration) . . . . .	55
Figure 5-3: GSM transmit power waveform (class 10 operation) . . . . .	56
Figure 7-1: Top view . . . . .	62
Figure 7-2: Dimensioned view . . . . .	63
Figure 7-3: Sample unit label . . . . .	63
Figure 7-4: Shield locations . . . . .	64
Figure 4-1: Device placement in module tray . . . . .	91
Figure 4-2: Shipping package . . . . .	91



# >> 1: Introduction

The Sierra Wireless MC7330 PCI Express Mini Card is a compact, lightweight, wireless [LTE](#)- and UMTS-based modem.

The MC7330 provides LTE, [DC-HSPA+](#), [HSPA+](#), [HSDPA](#), [HSUPA](#), [WCDMA](#), [GSM](#), [GPRS](#), [EDGE](#), and GNSS connectivity for networking, and M2M applications over several radio frequency bands. The device also supports 2G/3G roaming, subject to network operator provisioning.

The MC7330 will be Windows 8 Mobile Broadband Interface Model (MBIM) compliant.

## Supported RF bands

The modem, based on Qualcomm's MDM9215 baseband processor, supports data operation on LTE, DC-HSPA+, HSPA+, EDGE, GPRS and GSM networks.

**Table 1-1: Supported RF bands**

Technology	Bands	Notes	Data rates
<b>LTE</b>	<ul style="list-style-type: none"> <li>Band 1 (2100 MHz)</li> <li>Band 19 (850 MHz)</li> <li>Band 21 (1500 MHz)</li> </ul>	MIMO support	Category 3 <ul style="list-style-type: none"> <li>Downlink:               <ul style="list-style-type: none"> <li>100 Mbps (20 MHz bandwidth)</li> <li>50 Mbps (10 MHz bandwidth)</li> </ul> </li> <li>Uplink:               <ul style="list-style-type: none"> <li>50 Mbps (20 MHz bandwidth)</li> <li>25 Mbps (10 MHz bandwidth)</li> </ul> </li> </ul>
<b>UMTS (WCDMA) HSDPA HSUPA HSPA+ DC-HSPA+</b>	<ul style="list-style-type: none"> <li>Band 1 (2100 MHz)</li> <li>Band 5 (850 MHz)</li> <li>Band 6 (800 MHz)</li> <li>Band 19 (850 MHz)</li> </ul>	Diversity support	HSPA+ rates <ul style="list-style-type: none"> <li>Downlink: Up to 42 Mbps (category 24)</li> <li>Uplink: Up to 5.76 Mbps (category 6)</li> </ul>
<b>GSM GPRS EDGE</b>	<ul style="list-style-type: none"> <li>GSM 850 (850 MHz)</li> <li>EGSM 900 (900 MHz)</li> <li>DCS 1800 (1800 MHz)</li> <li>PCS 1900 (1900 MHz)</li> </ul>		EDGE throughput up to 236 kbps
<b>GNSS</b>	<ul style="list-style-type: none"> <li>GPS: 1575.42 MHz</li> <li>GLONASS: 1602 MHz</li> </ul>		

## Physical features

- Small form factor—conforms to type F2 as specified in *PCI Express Mini Card Electromechanical Specification Revision 1.2*.

- Temperature
  - Operating temperature range (Class A): -30°C to +70°C
  - Operating temperature range (Class B): -40°C to +85°C

---

**Important:** *The internal module temperature must be kept below 100°C. For best performance, the internal module temperature should be kept below 85°C. Proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.*

---

## Application interface features

- USB interface (QMI) for Windows 7 and legacy Windows operating systems
- MBIM for Windows 8
- USB Link Power Management (LPM2) combined with selective suspend to maximize power savings. Also supports fast wakeup.
- AT command interface ([1] *AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)*, plus proprietary extended AT commands in [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference (Doc# 4114486)*)
- Software Development Kits (SDK) for Windows 7 and Windows 8
- Linux SDK, including a Linux API (Application Program Interface)
- QDL loader compliant
- Support for active antenna control via dedicated antenna control signals (ANT\_CTRL0:2)
- Dynamic power reduction support via software and dedicated signal (DPR)

---

*Note: Dial-up networking (DUN) is not supported.*

---



## Modem features

**Table 1-2: Modem features**

- LTE/DC-HSPA+/HSPA+/HSPA/UMTS (WCDMA)/EDGE/GPRS operation
- Multiple (up to 16) cellular packet data profiles
- Traditional modem COM port support for AT commands
- USB suspend/resume
- Sleep mode for minimum idle power draw
- SIM application tool kit with proactive SIM commands
- Enhanced Operator Name String (EONS)
- Automatic GPRS attach at power-up
- GPRS detach
- GPRS detach only
- Combined GPRS / IMSI detach; MS-initiated and network-initiated detach
- Mobile-originated PDP context activation / deactivation
- Support QoS profile
  - Release 99 QoS negotiation—Background, Interactive, and Streaming
  - Release 97—Precedence Class, Reliability Class, Delay Class, Peak Throughput, Mean Throughput
- Static and Dynamic IP address. The network may assign a fixed IP address or dynamically assign one using DHCP (Dynamic Host Configuration Protocol).
- PAP and CHAP support
- PDP context type (IPv4, IPv6, or IPv4v6). IP Packet Data Protocol context.
- RFC1144 TCP/IP header compression
- Interaction with existing GSM services (MO / MT SMS) while:
  - GPRS is attached, or
  - In a GPRS data session (class B GPRS suspend / resume procedures)

## LTE features

- Basic cell selection and system acquisition
  - PSS/SSS/MIB decode
  - SIB1–SIB12 decoding
- NAS/AS security procedures
  - Snow 3G/AES security
- CQI/RI/PMI reporting
- Paging procedures
  - Paging in Idle and Connected mode

- Dedicated bearer
  - Network-initiated dedicated bearer
  - [UE](#)-initiated dedicated bearer
- Multiple PDN connections (IPv4 and IPv6 combinations), subject to operating system support. (For example, not supported in Windows 8.)
- Connected mode intra-LTE mobility
- Idle mode intra-LTE mobility
- iRAT between LTE/2G  
iRAT between LTE/3G for idle and connection release with redirection
- Detach procedure
  - Network-initiated detach with reattach required
  - Network-initiated detach followed by connection release

## Short Message Service (SMS) features

- Mobile-terminated [SMS](#) for UMTS
- Mobile-originated SMS for UMTS
- SMS over SGs (LTE)
- Mobile-terminated SMS over [IMS](#) for LTE
- Mobile-terminated SMS over GPRS/UMTS/HSPA

## Position location (GNSS)

- Concurrent standalone GPS and GLONASS
- Assisted GPS (A-GPS) SUPL1.0
- Assisted [GNSS](#) (A-GNSS) SUPL2.0
- gpsOneXTRA 2.0 with GPS + GLONASS support
- GNSS on dedicated connector or diversity connector
- DC bias on GNSS connector to support an external active GNSS antenna

## Warranty and support

The MC7330 offers the following support features:

- Standard 1-year warranty
- Enabling software (drivers, [SDK](#), etc.) for Android RIL (Radio Interface Layer) v4.0 (Ice Cream Sandwich) and later, Linux, Windows 7, and Windows 8

## Supporting documents

Several additional documents describe Mini Card design, usage, integration, and other features. See [References on page 93](#).

## Accessories

The Universal Development Kit (UDK) is a hardware development platform for AirPrime MC-series modules. It contains hardware components for evaluating and developing with the module, including:

- Development board
- Cables
- Antennas (Additional antennas may be required to support all bands.)
- Initial allotment of support hours
- Other accessories

For instructions on setting up the UDK (part number 6000270), see [3] *PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705)*.

For over-the-air LTE testing, ensure that suitable antennas are used. (Two antennas are required for this testing; Sierra Wireless offers an LTE-capable antenna covering 700–2600 MHz BW—please order part number 6000492 (Qty 1—this contains two antennas).)

## Required connectors

[Table 1-3](#) describes the connectors used to integrate AirPrime MC-series modules into your host device.

**Table 1-3: Required host-module connectors<sup>1</sup>**

Connector type	Description
RF cables	<ul style="list-style-type: none"> <li>• Mate with Hirose U.FL connectors (model U.FL #CL331-0471-0-10)</li> <li>• Three connector jacks (Note: The UDK has two connector jacks.)</li> </ul>
EDGE (52-pin)	<ul style="list-style-type: none"> <li>• Industry-standard mating connector</li> <li>• Some manufacturers include Tyco, Foxconn, Molex</li> <li>• Example: UDK board uses Molex 67910-0001</li> </ul>
<a href="#">SIM</a>	<ul style="list-style-type: none"> <li>• Industry-standard connector. Type depends on how host device exposes the SIM socket</li> <li>• Example: UDK board uses ITT CCM03-3518</li> </ul>

1. Manufacturers/part numbers are for reference only and are subject to change. Choose connectors that are appropriate for your own design.

## Ordering information

To order, contact the Sierra Wireless Sales Desk at +1 (604) 232-1488 between 8 AM and 5 PM Pacific Time.

## Integration requirements

Sierra Wireless provides, in the document suite, guidelines for successful Mini Card integration and offers integration support services as necessary.

When integrating the MC7330 PCI-Express Mini Card, the following items need to be addressed:

- **Mounting**—Effect on temperature, shock, and vibration performance
- **Power supply**—Impact on battery drain and possible [RF](#) interference
- **Antenna location and type**—Impact on RF performance
- **Regulatory approvals**—As discussed in [Regulatory Compliance and Industry Certifications on page 67](#).
- **Service provisioning**—Manufacturing process
- **Software**—As discussed in [Software Interface on page 59](#).
- **Host Interface**—Compliance with interface voltage levels

## >> 2: Standards Compliance

The MC7330 Mini Card complies with the mandatory requirements described in the following standards. The exact set of requirements supported is network operator-dependent.

**Table 2-1: Standards compliance**

Technology	Standards
LTE	<ul style="list-style-type: none"><li>• 3GPP Release 9</li></ul>
UMTS	<ul style="list-style-type: none"><li>• 3GPP Release 5</li><li>• 3GPP Release 6</li><li>• 3GPP Release 7</li><li>• 3GPP Release 8</li></ul>
GSM/GPRS/EDGE	<ul style="list-style-type: none"><li>• 3GPP Release 99</li><li>• GERAN Feature Package #1</li></ul>



## >> 3: Electrical Specifications

The system block diagram in [Figure 3-1 on page 24](#) represents the MC7330 module integrated into a host system. The module includes the following interfaces to the host:

- **Power**—Supplied to the module by the host.
- **W\_DISABLE\_N**—Active low input from a hardware switch to the MC7330 that disables the main RF radio.
- **WAKE\_N**—Signal used to wake the host when specific events occur.
- **WAN\_LED\_N**—Active-low [LED](#) drive signal provides an indication of RADIO ON state, either WAN or GNSS.
- **SYSTEM\_RESET\_N**—Active-low reset input.
- **Antenna**—Three U.FL [RF](#) connectors (one for Rx/Tx, one for Rx only, and one for GNSS). For details, see [RF Specifications on page 41](#).  
Note that GNSS can use either the dedicated GNSS port, or the diversity/[MIMO](#) port.
- **SIM**—Supported through the interface connector. The [SIM](#) cavity / connector must be placed on the host device for this feature.
- **USB**—Interface to the host for data, control, and status information.
- **Antenna control**—Three signals that can be used to control external antenna switches.
- **Dynamic power control**—Signal used to adjust Tx power to meet SAR requirements. For details, see [Tx power control on page 57](#).
- **PCM/I<sup>2</sup>S audio interface**—PCM or Inter-IC Sound (I<sup>2</sup>S) serial bus for digital audio.

The MC7330 has two main interface areas—the host I/O connector and the [RF](#) ports. Details of these interfaces are described in the sections that follow.

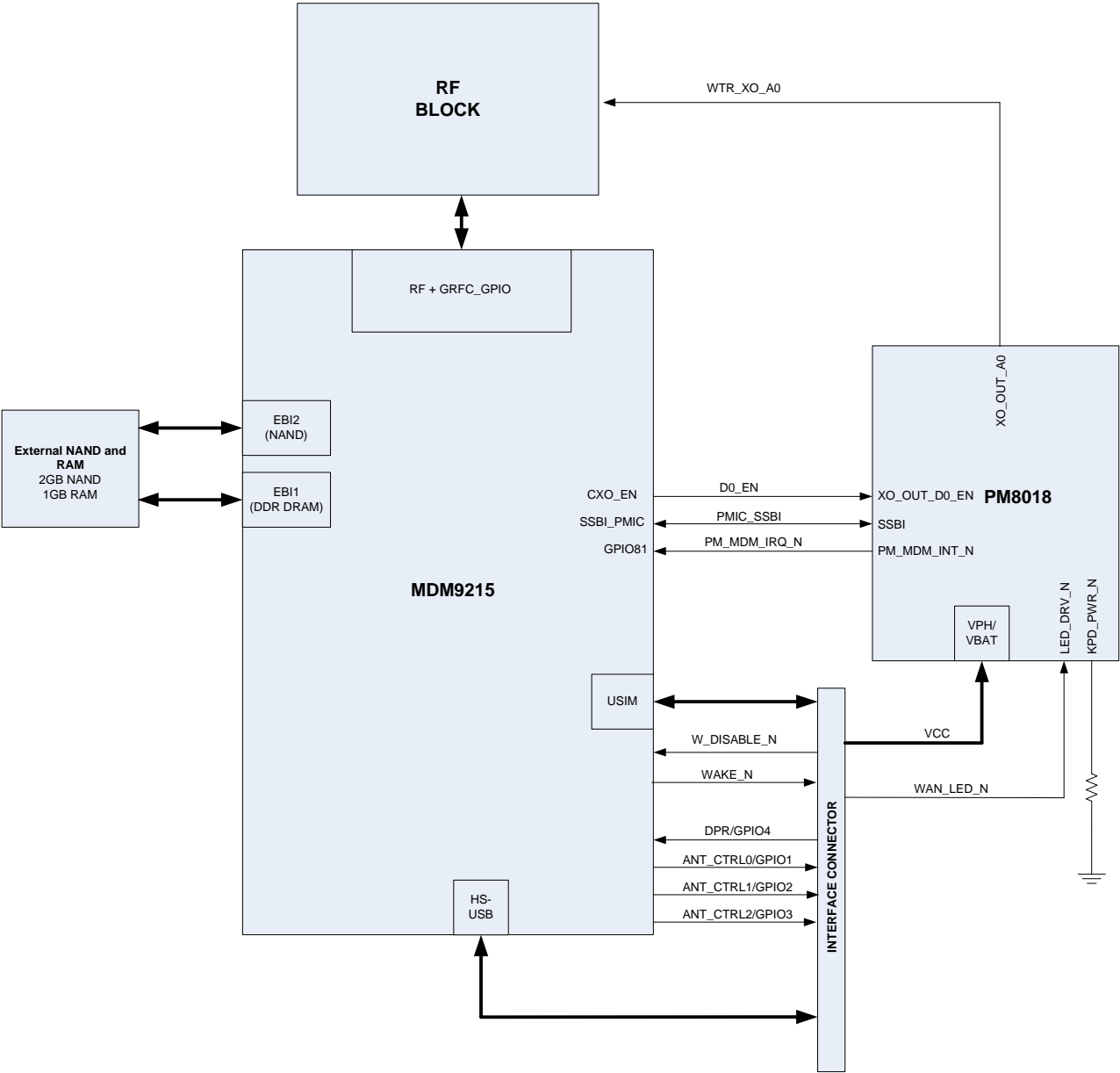


Figure 3-1: System block diagram



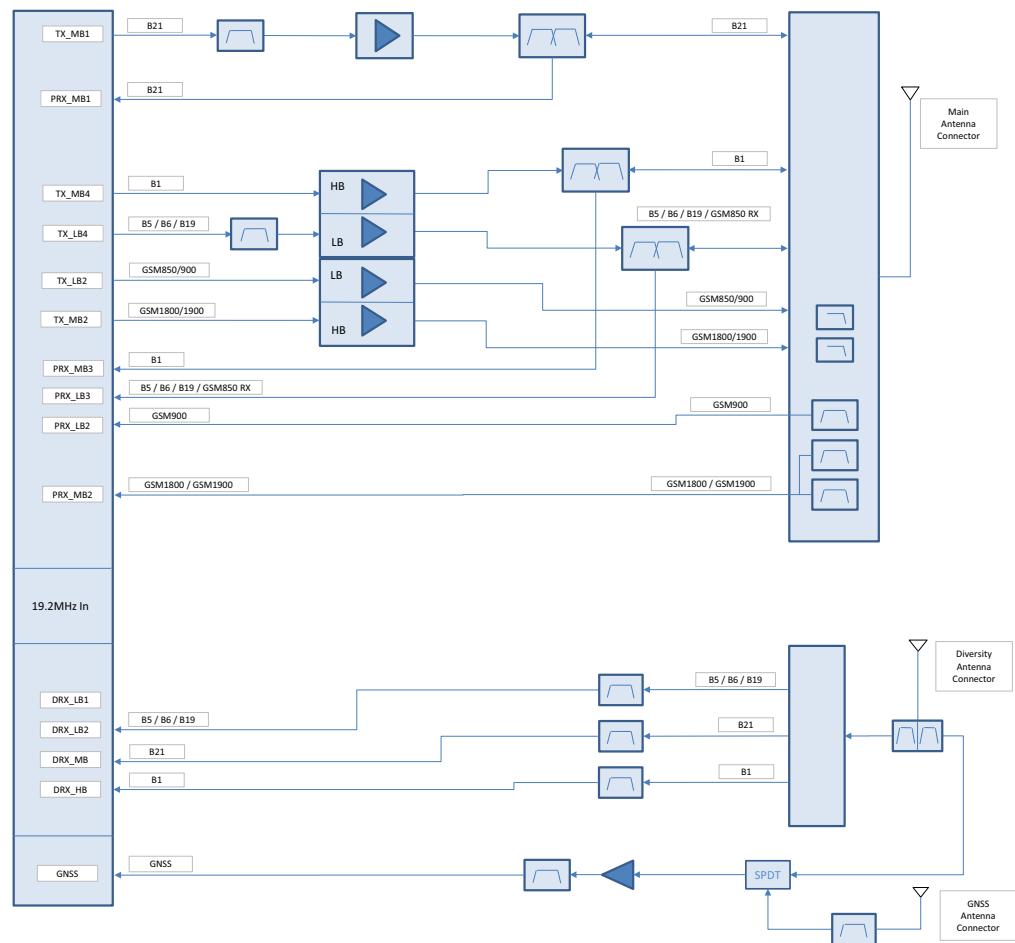


Figure 3-2: Expanded RF block diagram

## Host interface pin assignments

The MC7330 host I/O connector provides pins for power, serial communications, and control. Pin assignments are listed in [Table 3-1](#). See the following tables for pin details based on interface types:

- [Table 3-2, Power and ground specifications](#), on page 30
- [Table 3-3, USB interface](#), on page 30
- [Table 3-4, SIM interface signal](#), on page 31
- [Table 3-5, Module control signals](#), on page 34

*Note: On any given interface (USB, SIM, etc.), leave unused inputs and outputs as no-connects.*

Note: The following table describes the **internal** structure of the module.

Table 3-1: Connector pin assignments<sup>1</sup>

Pin	Signal name	Pin type <sup>2</sup>	Description	Direction to module	Active state	Voltage levels (V)		
						Min	Typ	Max
1	WAKE_N	OC	Wake host	Output	Low	-	-	0.10
2	VCC	V	Power supply	Input	Power	3.00	3.30	3.60
3	ANT_CTRL0 / GPIO1	-	(ANT_CTRL0) Customer-defined external switch control for multiple antennas	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45
			(GPIO1) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
4	GND	V	Ground	Input	Power	-	0	-
5	ANT_CTRL1 / GPIO2	-	(ANT_CTRL1) Customer-defined external switch control for multiple antennas	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45
			(GPIO2) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
6	NC	-	No connect	-	-	-	-	-
7	NC	-	No connect	-	-	-	-	-
8	USIM_PWR	-	SIM VCC supply	Output	Power	2.75 (3V SIM) 1.75 (1.8V SIM)	2.85 (3V SIM) 1.80 (1.8V SIM)	3.05 (3V SIM) 1.85 (1.8V SIM)
9	GND	V	Ground	Input	Power	-	0	-
10	USIM_DATA	-	SIM IO pin	Input	Low	-0.30 (3V SIM) -0.30 (1.8V SIM)	-	0.70 (3V SIM) 0.63 (1.8V SIM)
					High	1.85 (3V SIM) 1.17 (1.8V SIM)	2.85 (3V SIM) 1.80 (1.8V SIM)	3.15 (3V SIM) 2.10 (1.8V SIM)
				Output	Low	0	-	0.45
					High	2.40 (3V SIM) 1.35 (1.8V SIM)	-	2.85 (3V SIM) 1.90 (1.8V SIM)

**Table 3-1: Connector pin assignments<sup>1</sup> (Continued)**

Pin	Signal name	Pin type <sup>2</sup>	Description	Direction to module	Active state	Voltage levels (V)		
						Min	Typ	Max
11	VCC_MSM18_DIG <sup>3</sup>	-	1.8V reference voltage output	Output	Power	1.75	1.80	1.85
12	USIM_CLK	-	SIM Clock	Output	Low	0	-	0.45
					High	2.40 (3V SIM) 1.35 (1.8V SIM)	-	2.85 (3V SIM) 1.90 (1.8V SIM)
13	NC	-	No connect	-	-	-	-	-
14	USIM_RST	-	SIM Reset	Output	Low	0	-	0.45
					High	2.40 (3V SIM) 1.35 (1.8V SIM)	-	2.85 (3V SIM) 1.90 (1.8V SIM)
15	GND	V	Ground	Input	Power	-	0	-
16	NC	-	No connect	-	-	-	-	-
17	NC	-	No connect	-	-	-	-	-
18	GND	V	Ground	Input	Power	-	0	-
19	NC	-	No connect	-	-	-	-	-
20	W_DISABLE_N	-	Wireless Disable (main RF radio)	Input	Low	-	-	0.7
21	GND	V	Ground	Input	Power	-	0	-
22	NC	-	No connect	-	-	-	-	-
23	NC	-	No connect	-	-	-	-	-
24	VCC	V	Power supply	Input	Power	3.00	3.30	3.60
25	NC	-	No connect	-	-	-	-	-
26	GND	V	Ground	Input	Power	-	0	-
27	GND	V	Ground	Input	Power	-	0	-
28	NC	-	No connect	-	-	-	-	-
29	GND	V	Ground	Input	Power	-	0	-
30	I2C_CLK <sup>4,5</sup>	-	I2C serial bus clock	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
31	NC	-	No connect	-	-	-	-	-

**Table 3-1: Connector pin assignments<sup>1</sup> (Continued)**

Pin	Signal name	Pin type <sup>2</sup>	Description	Direction to module	Active state	Voltage levels (V)		
						Min	Typ	Max
32	I2C_DATA <sup>4,5</sup>	-	I2C serial bus data	Input High		1.17	1.80	2.10
				Input Low		-0.3		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
33	SYSTEM_RESET_N	-	Reset	Input	Low	-0.30	-	0.63
34	GND	V	Ground	Input	Power	-	0	-
35	GND	V	Ground	Input	Power	-	0	-
36	USB_D-	-	USB data negative	Input/Output	Differential	-	-	-
37	GND	V	Ground	Input	Power	-	0	-
38	USB_D+	-	USB data positive	Input/Output	Differential	-	-	-
39	VCC	V	Power supply	Input	Power	3.00	3.30	3.60
40	GND	V	Ground	Input	Power	-	0	-
41	VCC	V	Power supply	Input	Power	3.00	3.30	3.60
42	WAN_LED_N	OC	LED Driver	Output	Low	0	-	0.15
43	GND	V	Ground	Input	Power	-	0	-
44	ANT_CTRL2 / GPIO3	-	(ANT_CTRL2) Customer-defined external switch control for multiple antennas	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45
			(GPIO3) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
			(I2S_CLK) I <sup>2</sup> S Clock	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45
45	PCM_CLK / I2S_CLK <sup>6</sup>	-	(PCM_CLK) PCM Clock— Input in Slave mode, output in Master mode	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
			(I2S_CLK) I <sup>2</sup> S Clock	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45

**Table 3-1: Connector pin assignments<sup>1</sup> (Continued)**

Pin	Signal name	Pin type <sup>2</sup>	Description	Direction to module	Active state	Voltage levels (V)		
						Min	Typ	Max
46	DPR/ GPIO4	-	(DPR) Dynamic power control	Input	High	1.17	1.80	2.10
				Input	Low	-0.30	-	0.63
			(GPIO4) General purpose I/O	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
47	PCM_DOUT/ I <sup>2</sup> S_DOUT <sup>6</sup>	-	PCM Data Out/ I <sup>2</sup> S Data Out	Output	High	1.35	1.80	1.90
				Output	Low	0		0.45
48	NC	-	No connect	-	-	-	-	-
49	PCM_DIN/ I <sup>2</sup> S_DIN <sup>6</sup>	-	PCM Data In/ I <sup>2</sup> S Data In	Input	High	1.17	1.80	2.10
				Input	Low	-0.30		0.63
50	GND	V	Ground	Input	Power	-	0	-
51	PCM_WS / I <sup>2</sup> S_SYNC <sup>6</sup>	-	PCM Sync— Input in Slave mode, output in Master mode	Input High		1.17	1.80	2.10
				Input Low		-0.30		0.63
				Output High		1.35	1.80	1.90
				Output Low		0.00		0.45
			I <sup>2</sup> S WS	Output	High	1.35	-	1.90
				Output	Low	0	-	0.45
52	VCC	V	Power supply	Input	Power	3.00	3.30	3.60

1. The host should leave all 'NC' ('no connect') pins unconnected.

2. A—Analog; I—Input; NP—No pull; O—Digital output; OC—Open Collector; PU—Digital input (internal pull up); PD—Digital output (internal pull down); V—Power or ground

3. To avoid adverse effects on module operation, do not draw more than 10 mA current on pin 11.

4. Leave both I2C pins as No Connect if I2C interface is not used.

5. Clock speed: 400 kHz

6. PCM Master/Slave mode and I2S Master mode are supported.

## Power supply

The host provides power to the MC7330 through multiple power and ground pins as summarized in [Table 3-2](#).

The host must provide safe and continuous power at all times; the module does not have an independent power supply, or protection circuits to guard against electrical issues.

**Table 3-2: Power and ground specifications**

Name	Pins	Specification	Min	Typ	Max	Units
VCC	2, 24, 39, 41, 52	Voltage range	See <a href="#">Table 3-1 on page 26</a> .			
		Ripple voltage	-	-	100	mV <sub>pp</sub>
GND	4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50	-	-	0	-	V

## USB interface

*Note: Host support for USB signals is required.*

The USB interface is the path for communication between the host and module.

The interface complies with the [10] *Universal Serial Bus Specification, Rev 2.0*, and the host device must be designed to the same standard. (When designing the host device, careful PCB layout practices must be followed.)

**Table 3-3: USB interface**

Name	Pin	Description
USB_D-	36	USB data negative
USB_D+	38	USB data positive

USB interface features include:

- Data rate: Full-speed (12 Mbps)/High-speed (480 Mbps)
- Module enumeration:
  - Windows: Modem or COM ports, using host Windows drivers
  - Linux: /dev/ttyUSB*n* devices for Linux systems with the Sierra Wireless driver installed
- USB-compliant transceivers
- Selective suspend mode
- Resumption initiated by host or module

## USB high/full speed throughput performance

This device has been designed to achieve optimal performance and maximum throughput using USB high speed mode. Although the device may operate with a full speed host, throughput performance will be on an “as is” basis and needs to be characterized by the [OEM](#). Note that throughput will be reduced and may vary significantly based on [packet](#) size, host interface, and [firmware](#) revision. Sierra Wireless does not recommend using this device in USB full speed mode.

## User-developed drivers

If you will be developing your own USB drivers, see *[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)*.

## SIM interface

*Note: Host support for SIM interface signals is required.*

The module supports one SIM (Subscriber Identity Module) (1.8 V or 3 V). The SIM holds account information, allowing users to use their account on multiple devices.

The [SIM](#) pins ([Table 3-4](#)) provide the connections necessary to interface to a SIM socket located on the host device as shown in [Figure 3-3 on page 32](#). Voltage levels over this interface comply with 3GPP standards.

**Table 3-4: SIM interface signal**

Name	Pin	Description	SIM contact number <sup>1</sup>	Notes
USIM_PWR	8	SIM voltage	1	Power supply for SIM
USIM_DATA	10	Data I/O	7	Bi-directional SIM data line
USIM_CLK	12	Serial clock	3	Serial clock for SIM data
USIM_RST	14	Reset	2	Active low SIM reset
USIM_GND		Ground	5	Ground reference USIM_GND is common to module ground

1. See [Figure 3-4 on page 32](#) for SIM card contacts.

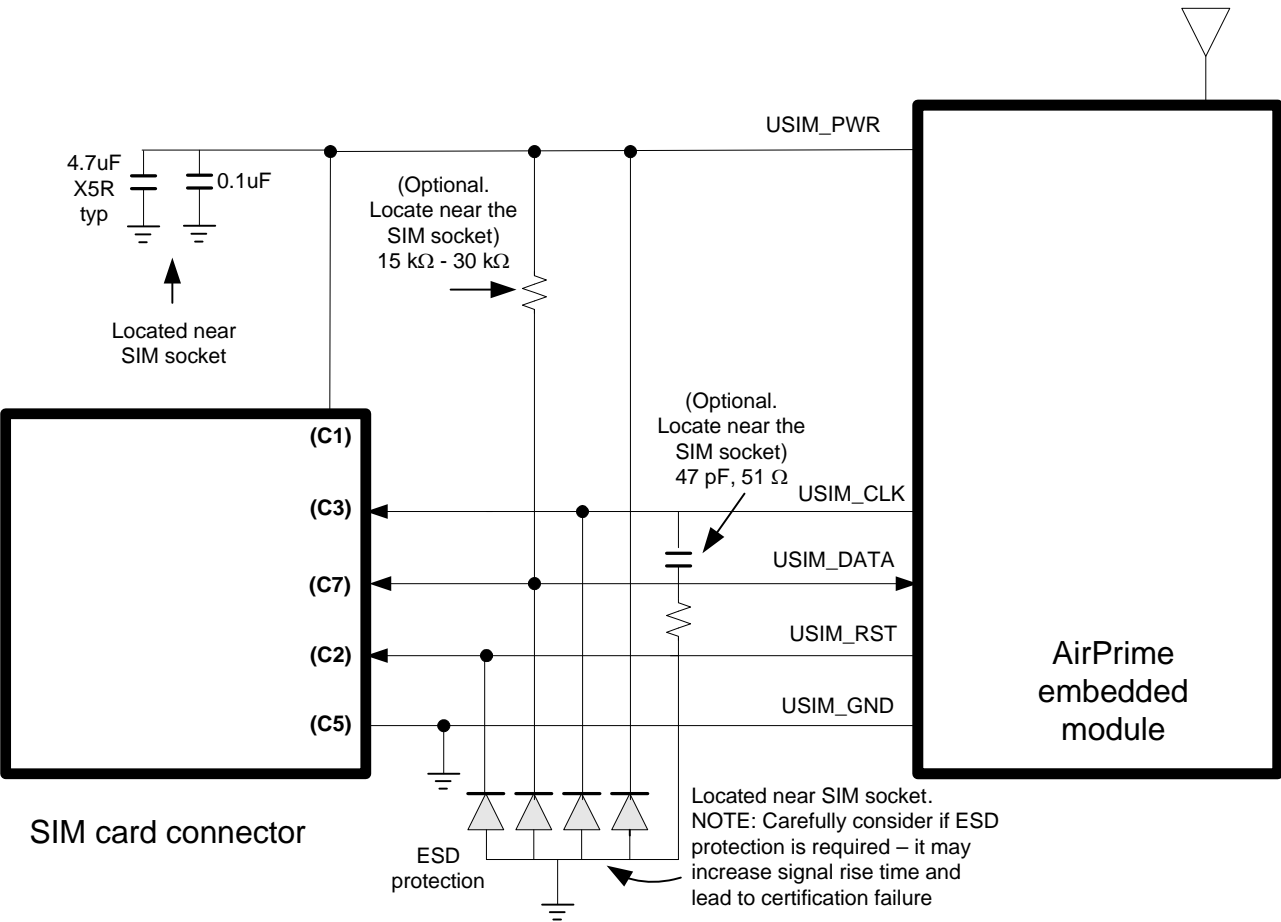


Figure 3-3: SIM application interface

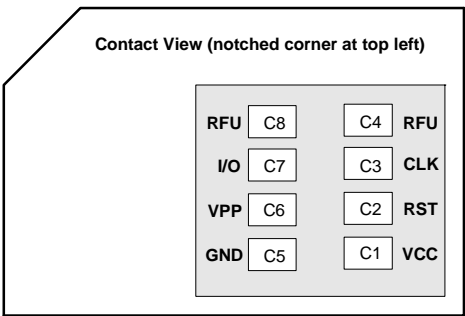


Figure 3-4: SIM card contacts (contact view)



## SIM implementation

---

*Note: For interface design requirements, refer to: (2G) 3GPP TS 51.010-1, section 27.17, or (3G) ETSI TS 102 230 V5.5.0, section 5.2.*

---

When designing the remote SIM interface, you *must* make sure that SIM signal integrity is not compromised.

Some design recommendations include:

- Total impedance of the VCC and GND connections to the SIM, measured at the module connector, should be less than  $1\ \Omega$  to minimize voltage drop (includes any trace impedance and lumped element components—inductors, filters, etc.).
- Position the SIM connector  $\leq 10$  cm from the module. If a longer distance is required because of the host device design, use a shielded wire assembly—connect one end as close as possible to the SIM connector and the other end as close as possible to the module connector. The shielded assembly may help shield the SIM interface from system noise.
- Reduce crosstalk on the USIM\_DATA line to reduce the risk of failures during GCF approval testing.
- Avoid routing the USIM\_CLK and USIM\_DATA lines in parallel over distances  $> 2$  cm—cross-coupling of these lines can cause failures.
- 3GPP has stringent requirements for I/O rise time ( $< 1\ \mu\text{s}$ ), signal level limits, and noise immunity—consider this carefully when developing your PCB layout.
  - Keep signal rise time  $< 1\ \mu\text{s}$ —keep USIM signals as short as possible, and keep very low capacitance traces on the USIM\_DATA and USIM\_CLK signals. High capacitance increases signal rise time, potentially causing your device to fail certification tests.
- Add external pull-up resistors ( $15\ \text{k}\Omega$ – $30\ \text{k}\Omega$ ), if required, between the USIM\_DATA and USIM\_PWR lines to optimize the signal rise time.
- VCC line should be decoupled close to the SIM socket.
- SIM is specified to run up to 5 MHz (SIM clock rate). Take note of this speed in the placement and routing of the SIM signals and connectors.
- You must decide whether additional ESD protection is required for your product, as it is dependent on the application, mechanical enclosure, and SIM connector design. The SIM pins will require additional ESD protection if they are exposed to high ESD levels (i.e. can be touched by a user).
- Putting an optional decoupling capacitor at USIM\_PWR near the SIM socket is recommended—the longer the trace length (impedance) from the socket to the module, the greater the capacitance requirement to meet compliance tests.
- Putting an optional series capacitor and resistor termination (to ground) at USIM\_CLK at the SIM socket to reduce EMI and increase signal integrity is recommended if the trace length between the SIM socket and module is long— $47\ \text{pF}$  and  $50\ \Omega$  resistor are recommended.
- Test your first prototype host hardware with a Comprion IT<sup>3</sup> SIM test device at a suitable testing facility.

# Control interface (Signals)

The MC7330 provides signals for:

- Waking the host when specific events occur
- Host control of the module's radios
- LED driver output

These signals are summarized in [Table 3-5](#) and paragraphs that follow.

**Table 3-5: Module control signals**

Name	Pin	Description	Type <sup>1</sup>
WAKE_N	1	Wake host	OC
W_DISABLE_N	20	Wireless disable (Main RF)	PU
WAN_LED_N	42	LED driver	OC

1. OC—Open Collector; PU—Digital pin Input, internal pull up

## WAKE\_N — Wake host

*Note: Host support for WAKE\_N is optional.*

The module uses WAKE\_N to wake the host when specific events occur. (Support for this signal is firmware-dependent. Contact your Sierra Wireless account representative to determine specific availability.)

The host must provide a 5 k $\Omega$ –100 k $\Omega$  pullup resistor that considers total line capacitance (including parasitic capacitance) such that when WAKE\_N is deasserted, the line will rise to 3.3 V (Host power rail) in < 100 ns.

See [Figure 3-5 on page 34](#) for a recommended implementation.

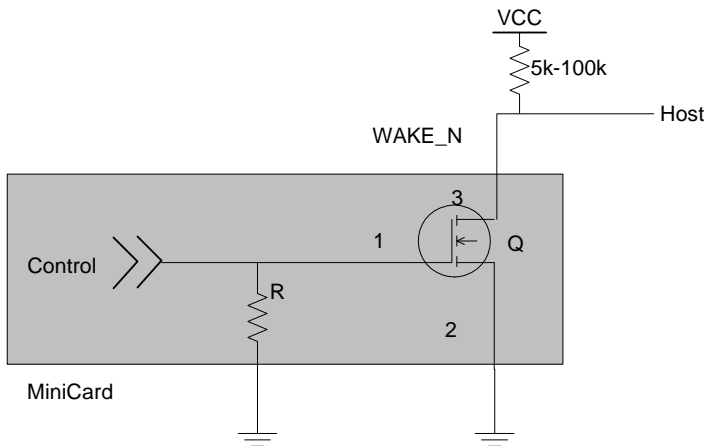


Figure 3-5: Recommended WAKE\_N connection

## W\_DISABLE\_N — Wireless disable

*Note: Host support for wireless disable signals is optional.*

The host device uses W\_DISABLE\_N (pin 20) to enable/disable the WWAN or radio modem. When disabled, the modem cannot transmit or receive information.

Letting this signal float high allows the module to operate normally. This switch follows the behavior described in [9] *PCI Express Mini Card Electromechanical Specification Revision 1.2*. This pin has a 20 k $\Omega$  pull-up resistor. See [Figure 3-6 on page 35](#) for a recommended implementation.

When integrating with your host device, keep the following in mind:

- The signal is an input to the module and should be driven LOW only for its active state (controlling the power state); otherwise it should be floating or (High impedance). It should never be driven to a logic high level. The module has an internal pull-up resistor to Module Power (3.3V) in place, so if the signal is floating or (high impedance), then the radio is on.
- Wait for two seconds after asserting W\_DISABLE\_N before disconnecting power.
- If the host never needs to assert this power state control to the module, leave this signal unconnected from the host interface.

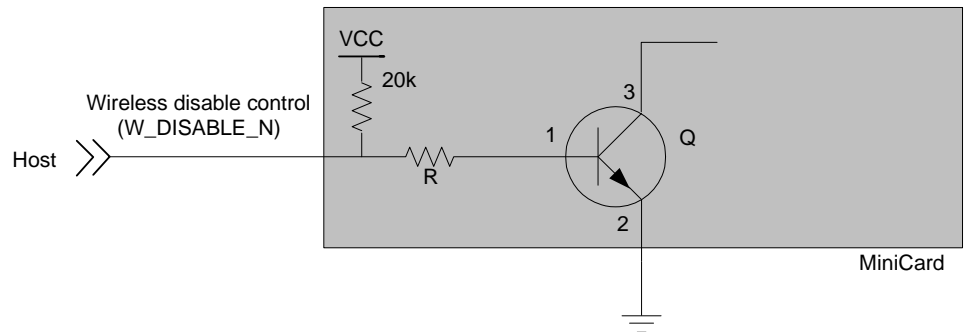


Figure 3-6: Recommended wireless disable connection

## WAN\_LED\_N—LED output

*Note: Host support for WAN\_LED\_N is optional.*

The module drives the LED output according to [9] *PCI Express Mini Card Electromechanical Specification Revision 1.2*.

*Note: The LED configuration is customizable. Contact your Sierra Wireless account representative for details.*

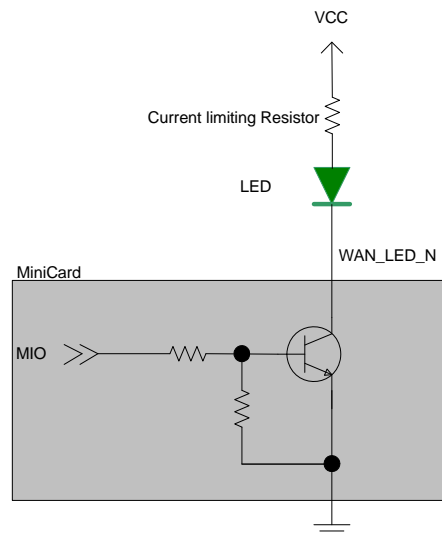


Figure 3-7: Example LED

## SYSTEM\_RESET\_N—Reset Input

*Note: Host support for SYSTEM\_RESET\_N is optional.*

SYSTEM\_RESET\_N has an internal 1.8 V internal pull up. Set this signal to active low to reset the device. Note that the minimum pulse width is 250 ms.

## PCM/I2S Audio Interface

*Note: Voice is an optional feature that will be activated only on specific SKUs.*

*Note: PCM Master/Slave mode, Auxiliary PCM mode, and I2S Master modes are supported; I2S Slave mode is not supported. The default setting is PCM slave mode.*

The module implements a PCM/I2S digital audio interface using a dedicated serial link for digital audio data; all other signals, such as subcoding and control, are transmitted separately. The audio interface could be switchable via AT command between PCM and I2S. The PCM/I2S signals are summarized in the following table.

**Table 3-6: PCM/I2S Interface signals**

Signal name	Pin	Description
PCM_CLK/I2S_CLK	45	PCM Clock/I2S Clock
PCM_DOUT/I2S_DOUT	47	PCM Data Out/I2S Data Out
PCM_DIN/I2S_DIN	49	PCM Data In/I2S Data In
PCM_SYNC/I2S_WS	51	PCM SYNC/I2S WS

## PCM

The PCM interface implementation details include:

- Modes: Master and slave
- Sampling rates: 8 kHz, 16 kHz
- Audio compression formats: Linear,  $\mu$ -law, A-Law
- Padding: Disabled, enabled
- Bits per frame: 8, 16, 32, 64, 128, 256
- Bit frequency: (Sampling rate \* Bits per frame)

Figure 3-8, Figure 3-9 and Figure 3-10, and Table 3-7 below describe the PCM interface timing.

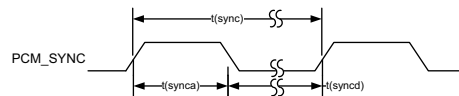


Figure 3-8: PCM\_SYNC timing

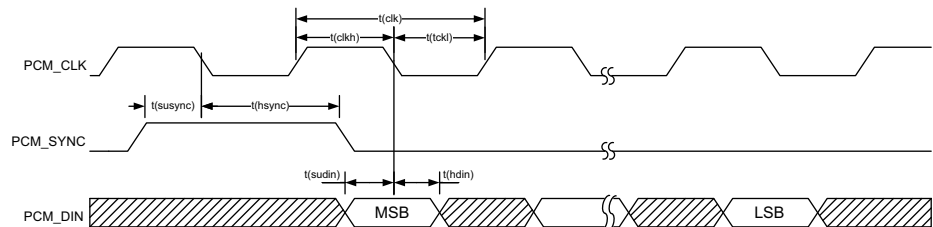


Figure 3-9: Timing—PCM\_CODEC to Module

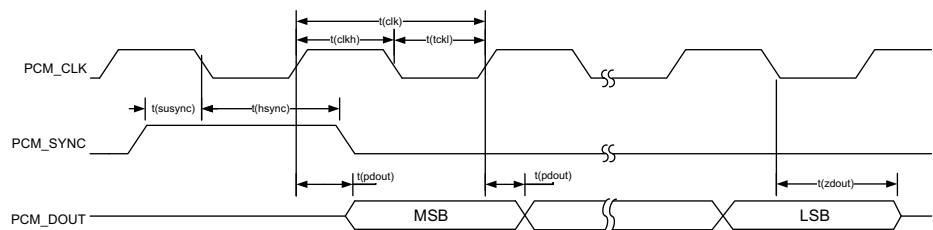


Figure 3-10: Timing—Module to PCM\_CODEC

**Table 3-7: PCM Timing<sup>1</sup>**

Parameter	Description	Min	Typ	Max	Unit
<b>T(sync)</b>	PCM_FS cycle time	-	125	-	$\mu$ s
<b>T(syncb)</b>	PCM_FS high time	-	488	-	ns
<b>T(synccl)</b>	PCM_FS low time	-	124.5	-	$\mu$ s
<b>T(clk)</b>	PCM_CLK cycle time	-	488	-	ns
<b>T(clkh)</b>	PCM_CLK high time	-	244	-	ns
<b>T(clkl)</b>	PCM_CLK low time	-	244	-	ns

**Table 3-7: PCM Timing<sup>1</sup> (Continued)**

Parameter	Description	Min	Typ	Max	Unit
<b>T(sync_offset)</b>	PCM_SYNC offset time to PCM_CLK falling	-	122	-	ns
<b>T(sudin)</b>	PCM_DIN setup time before falling edge of PCM_CLK	60	-	-	ns
<b>T(hdin)</b>	PCM_DIN hold time after falling edge of PCM_CLK	60	-	-	ns
<b>T(pdout)</b>	Delay from PCM_CLK rising to PCM_DOUT valid	-	-	60	ns
<b>T(zdout)</b>	Delay from PCM_CLK falling to PCM_DOUT HIGH-Z	-	-	60	ns

1. Maximum PCM clock rate is 2.048 MHz.

## I2S

The I2S can be used to transfer serial digital audio to/from an external stereo DAC/ADC. Interface implementation details include:

- Modes: Master (Slave mode is not supported)
- Sampling rates: 48 kHz
- Bits per frame: 16
- Bit clock: 1536 kHz

Figure 3-11 and Table 3-8 describe the I2S interface timing (per the Philips I2S bus timing specification).

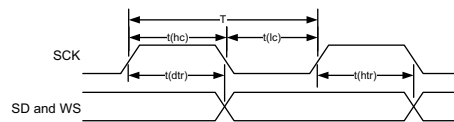


Figure 3-11: I2S transmitter timing

**Table 3-8: I2S master transmitter timing<sup>1,2</sup>**

Parameter	Description	Condition	Min	Typ	Max	Unit
<b>T</b>	Clock period	I2S requirement: min T=293	293	326	359	ns
<b>t(hc)</b>	Clock high	I2S requirement: min > 0.35T	120	-	-	ns
<b>t(lc)</b>	Clock low	I2S requirement: min > 0.35T	120	-	-	ns
<b>t(dtr)</b>	Delay	I2S requirement: Max < 0.8T	-	-	250	ns
<b>t(htr)</b>	Hold time	I2S requirement: min > 0	1--	-	-	ns

1. Bit clock: 1536 KHz (±10%)

2. Sample rate: 48 KHz (16 bits per sample)

## Antenna control

*Note: Host support for antenna control signals is optional.*

The MC7330 Mini Card provides three output signals that may be used for host designs that incorporate tunable antennas. For details, see [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference (Doc# 4114486)*.

**Table 3-9: Antenna control signals**

Name	Pin	Description
ANT_CTRL0	3	Customer-defined external switch control for tunable antennas
ANT_CTRL1	5	
ANT_CTRL2	44	





## 4: RF Specifications

The MC7330 includes three [RF](#) connectors for use with host-supplied antennas:

- Main RF connector—Rx/Tx path
- GNSS connector 1—Dedicated GNSS
- Diversity/MIMO/GNSS connector 2—Diversity, MIMO, or GNSS

The module does not have integrated antennas.

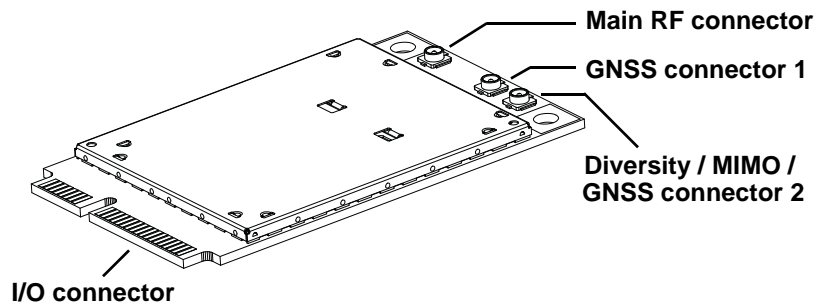


Figure 4-1: Module connectors

### RF connections

When attaching antennas to the module:

- Use Hirose U.FL connectors (3 mm x 3 mm, low profile; model U.FL #CL331-0471-0-10) to attach antennas to connection points on the module, as shown in [Figure 4-1](#) on page 41.
- Match coaxial connections between the module and the antenna to 50  $\Omega$ .
- Minimize RF cable losses to the antenna; the recommended maximum cable loss for antenna cabling is 0.5 dB.
- To ensure best thermal performance, mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.

---

*Note: To **disconnect** the antenna, make sure you use the Hirose U.FL connector removal tool (P/N UFL-LP-N-2(01)) to prevent damage to the module or coaxial cable assembly.*

---



---

*Note: If the antenna connection is shorted or open, the modem will not sustain permanent damage.*

---

### Shielding

The module is fully shielded to protect against EMI and must not be removed.

## Antenna and cabling

When selecting the antenna and cable, it is critical to RF performance to optimize antenna gain and cable loss.

---

*Note: For detailed electrical performance criteria, see [Appendix A: Antenna Specification](#) on page 69.*

---

### Choosing the correct antenna and cabling

When matching antennas and cabling:

- The antenna (and associated circuitry) should have a nominal impedance of 50  $\Omega$  with a recommended return loss of better than 10 dB across each frequency band of operation.
- The system gain value affects both radiated power *and* regulatory (FCC, IC, CE, etc.) test results.

### Designing custom antennas

Consider the following points when designing custom antennas:

- A skilled RF engineer should do the development to ensure that the RF performance is maintained.
- If both CDMA and UMTS modules will be installed in the same platform, you may want to develop separate antennas for maximum performance.

### Determining the antenna's location

When deciding where to put the antennas:

- Antenna location may affect RF performance. Although the module is shielded to prevent interference in most applications, the placement of the antenna is still very important—if the host device is insufficiently shielded, high levels of broadband noise or spurious interference can degrade the module's performance.
- Connecting cables between the module and the antenna must have 50  $\Omega$  impedance. If the impedance of the module is mismatched, RF performance is reduced significantly.
- Antenna cables should be routed, if possible, away from noise sources (switching power supplies, LCD assemblies, etc.). If the cables are near the noise sources, the noise may be coupled into the RF cable and into the antenna. See [Interference from other wireless devices on page 43](#).

### Disabling the diversity antenna

- Use the AT command `IRXDEN=0` to disable receive diversity or `IRXDEN=1` to enable receive diversity.

---

*Note: A diversity antenna is used to improve connection quality and reliability through redundancy. Because two antennas may experience different interference effects (signal distortion, delay, etc.), when one antenna receives a degraded signal, the other may not be similarly affected.*

---

## Ground connection

When connecting the module to system ground:

- Prevent noise leakage by establishing a very good ground connection to the module through the host connector.
- Connect to system ground using the two mounting holes at the top of the module (shown in [Figure 4-1](#) on page 41).
- Minimize ground noise leakage into the RF.  
Depending on the host board design, noise could *potentially* be coupled to the module from the host board. This is mainly an issue for host designs that have signals traveling along the length of the module, or circuitry operating at both ends of the module interconnects.

## Interference and sensitivity

Several interference sources can affect the module's RF performance (RF desense). Common sources include power supply noise and device-generated RF.

RF desense can be addressed through a combination of mitigation techniques ([Methods to mitigate decreased Rx performance on page 44](#)) and radiated sensitivity measurement ([Radiated sensitivity measurement on page 44](#)).

---

*Note: The MC7330 is based on ZIF (Zero Intermediate Frequency) technologies. When performing EMC (Electromagnetic Compatibility) tests, there are no IF (Intermediate Frequency) components from the module to consider.*

---

## Interference from other wireless devices

Wireless devices operating inside the host device can cause interference that affects the module.

To determine the most suitable locations for antennas on your host device, evaluate each wireless device's radio system, considering the following:

- Any harmonics, sub-harmonics, or cross-products of signals generated by wireless devices that fall in the module's Rx range may cause spurious response, resulting in decreased Rx performance.
- The Tx power and corresponding broadband noise of other wireless devices may overload or increase the noise floor of the module's receiver, resulting in Rx desense.

The severity of this interference depends on the closeness of the other antennas to the module's antenna. To determine suitable locations for each wireless device's antenna, thoroughly evaluate your host device's design.

## Host-generated RF interference

All electronic computing devices generate RF interference that can negatively affect the receive sensitivity of the module.

Proximity of host electronics to the antenna in wireless devices can contribute to decreased Rx performance. Components that are most likely to cause this include:

- Microprocessor and memory
- Display panel and display drivers
- Switching-mode power supplies

## Device-generated RF interference

The module can cause interference with other devices. Wireless devices such as AirPrime embedded modules transmit in bursts (pulse transients) for set durations (RF burst frequencies). Hearing aids and speakers convert these burst frequencies into audible frequencies, resulting in audible noise.

## Methods to mitigate decreased Rx performance

It is important to investigate sources of localized interference early in the design cycle. To reduce the effect of device-generated RF on Rx performance:

- Put the antenna as far as possible from sources of interference.
- Shield the host device. The module itself is well shielded to avoid external interference. In most instances, it is necessary to employ shielding on the components of the host device (such as the main processor and parallel bus) that have the highest RF emissions.
- Filter out unwanted high-order harmonic energy by using discrete filtering on low frequency lines.
- Form shielding layers around high-speed clock traces by using multi-layer PCBs.
- Route antenna cables away from noise sources.

## Radiated sensitivity measurement

A wireless host device contains many noise sources that contribute to a reduction in Rx performance.

To determine the extent of any receiver performance desensitization due to self-generated noise in the host device, over-the-air (OTA) or radiated testing is required. This testing can be performed by Sierra Wireless or you can use your own OTA test chamber for in-house testing.

## Sierra Wireless' sensitivity testing and desensitization investigation

Although AirPrime embedded modules are designed to meet network operator requirements for receiver performance, they are still susceptible to various performance inhibitors.

As part of the Engineering Services package, Sierra Wireless offers modem OTA sensitivity testing and desensitization (desense) investigation. For more information, contact your account manager or the Sales Desk (see [Contact Information on page 4](#)).

---

*Note: Sierra Wireless has the capability to measure TIS (Total Isotropic Sensitivity) and TRP (Total Radiated Power) according to CTIA's published test procedure.*

---

## Sensitivity vs. frequency

Sensitivity is defined as the input power level in dBm that produces a BER (Bit Error Rate) of 2% (GSM) or 0.1% (UMTS). Sensitivity should be measured at all GSM / UMTS frequencies across each band.

For LTE bands, sensitivity is defined as the RF level at which throughput is 95% of maximum.

## Supported frequencies

The MC7330 supports:

- Tri-band LTE—See [Table 4-1 on page 45](#).
- Quad-band WCDMA/HSDPA/HSUPA/HSPA+/DC-HSPA+—See [Table 4-3 on page 46](#).
- Quad-band WCDMA receive diversity
- Quad-band GSM/GPRS/EDGE—See [Table 4-4 on page 46](#).
- GPS and GLONASS—See [Table 4-9 on page 48](#).
- Inter-RAT and inter-frequency cell reselection and handover between supported frequency bands

**Table 4-1: LTE frequency band support**

Band	Frequencies
Band 1	Tx: 1920–1980 MHz Rx: 2110–2170 MHz
Band 19	Tx: 830–845 MHz Rx: 875–890 MHz
Band 21	Tx: 1447.9–1462.9 MHz Rx: 1495.9–1510.9 MHz

**Table 4-2: LTE bandwidth support<sup>1</sup>**

Band	1.4 MHz	3 MHz	5 MHz	10 MHz	15 MHz	20 MHz
Band 1	✗	✗	✓	✓	✓ <sup>2</sup>	✓ <sup>2</sup>
Band 19	✗	✗	✓	✓ <sup>2</sup>	✓ <sup>2</sup>	✗
Band 21	✗	✗	✓	✓ <sup>2</sup>	✓ <sup>2</sup>	✗

1. Table contents are derived from 3GPP TS 36.521-1 v9.4.1, table 5.4.2.1-1.

2. Bandwidth for which a relaxation of the specified UE receiver sensitivity requirement (Clause 7.3 of 3GPP TS 36.521-1 v9.4.1) is allowed.

**Table 4-3: WCDMA frequency band support<sup>1</sup>**

Band	Frequencies
Band 1 WCDMA 2100	Tx: 1920–1980 MHz Rx: 2110–2170 MHz
Band 5 WCDMA 850	Tx: 824–849 MHz Rx: 869–894 MHz
Band 6 WCDMA 800	Tx: 830–840 MHz Rx: 875–885 MHz
Band 19 WCDMA 850	Tx: 830–845 MHz Rx: 875–890 MHz

1. WCDMA channel spacing is 5 MHz, but this can be adjusted to optimize performance in a particular deployment scenario.

**Table 4-4: GSM frequency band support**

Band	Frequencies
GSM 850	Tx: 824–849 MHz Rx: 869–894 MHz
EGSM 900	Tx: 880–915 MHz Rx: 925–960 MHz
DCS 1800	Tx: 1710–1785 MHz Rx: 1805–1880 MHz
PCS 1900	Tx: 1850–1910 MHz Rx: 1930–1990 MHz

## Conducted Rx sensitivity / Tx power

**Table 4-5: Conducted Rx (Receive) sensitivity — LTE bands**

LTE bands		Conducted Rx sensitivity (dBm)			
		Primary (Typical)	Secondary (Typical)	SIMO (Typical)	SIMO <sup>1</sup> (Worst case)
LTE Band 1	Full RB BW: 10 MHz <sup>2</sup>	-98.9	-99.0	-102.0	-96.3
LTE Band 19		-99.5	-99.4	-102.6	-96.3
LTE Band 21		-99.5	-99.2	-102.4	-96.3

1. Per 3GPP specification  
 2. Sensitivity values scale with bandwidth:  

$$x\_MHz\_Sensitivity = 10\_MHz\_Sensitivity - 10 \cdot \log(10 \text{ MHz} / x\_MHz)$$

**Table 4-6: Conducted Rx (Receive) sensitivity — UMTS bands**

UMTS bands		Conducted Rx sensitivity (dBm)		
		Primary (Typical)	Secondary (Typical)	Primary/Secondary (Worst case) <sup>1</sup>
Band 1 (UMTS 2100)	0.1% BER 12.2 kbps	-111.7	-111.6	-106.7
Band 5 (UMTS 850)		-112.3	-111.9	-104.7
Band 6 (UMTS 850)		-112.1	-112.5	-106.7
Band 19 (UMTS 850)		-112.3	-112.3	-106.7

1. Per 3GPP specification.

**Table 4-7: Conducted Rx (Receive) sensitivity — GSM/EDGE bands**

GSM/EDGE bands			Conducted Rx sensitivity (dBm)	
			Typical	Worst case <sup>1</sup>
GSM 850	2% BER	CS <sup>2</sup>	-109	-102
	10% BLER	GMSK (CS1)	-111	-104
		EDGE (MCS5)	-102	-98
EGSM 900	2% BER	CS <sup>2</sup>	-109	-102
	10% BLER	GMSK (CS1)	-111	-104
		EDGE (MCS5)	-102	-98
DCS 1800	2% BER	CS <sup>2</sup>	-108	-102
	10% BLER	GMSK (CS1)	-111	-104
		EDGE (MCS5)	-101	-98
PCS 1900	2% BER	CS <sup>2</sup>	-108	-102
	10% BLER	GMSK (CS1)	-111	-104
		EDGE (MCS5)	-101	-98

1. Per 3GPP specification.

2. CS=Circuit Switched

**Table 4-8: Conducted Tx (Transmit) power tolerances**

Parameter	Conducted transmit power	Notes
LTE		
LTE Band 1,19, 21	+23 dBm $\pm$ 1 dB	

**Table 4-8: Conducted Tx (Transmit) power tolerances (Continued)**

Parameter	Conducted transmit power	Notes
<b>UMTS</b>		
Band 1 (IMT 2100 12.2 kbps) Band 5 (UMTS 850 12.2 kbps) Band 6 (UMTS 800 12.2 kbps) Band 19 (UMTS 850 12.2 kbps)	+23 dBm $\pm$ 1 dB	Connectorized (Class 3)
<b>GSM / EDGE</b>		
GSM850 CS EGSM900 CS	+32 dBm $\pm$ 1 dB	GMSK mode, connectorized (Class 4; 2 W, 33 dBm)
	+27 dBm $\pm$ 1 dB	8PSK mode, connectorized (Class E2; 0.5 W, 27 dBm)
DCS1800 CS PCS1900 CS	+29 dBm $\pm$ 1 dB	GMSK mode, connectorized (Class 1; 1 W, 30 dBm)
	+26 dBm $\pm$ 1 dB	8PSK mode, connectorized (Class E2; 0.4 W, 26 dBm)

## GNSS specifications

*Note: For detailed electrical performance criteria, see [Recommended GNSS antenna specifications on page 71](#).*

**Table 4-9: GNSS specifications**

Parameter/feature	Description
Satellite channels	Maximum 30 channels (16 GPS, 14 GLONASS), simultaneous tracking
Protocols	NMEA 0183 V3.0
Acquisition time	Hot start: 1 s Warm start: 29 s Cold start: 32 s
Accuracy	Horizontal: < 2 m (50%); < 5 m (90%) Altitude: < 4 m (50%); < 8 m (90%) Velocity: < 0.2 m/s
Sensitivity	Tracking <sup>1</sup> : -161 dBm Acquisition <sup>2</sup> (Assisted): -158 dBm Acquisition (Standalone): -145 dBm
Operational limits	Altitude < 6000 m or velocity < 100 m/s (Either limit may be exceeded, but not both.)

1. Tracking sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time when in sequential tracking mode.



2. Acquisition sensitivity is the lowest GNSS signal level for which the device can still detect an in-view satellite 50% of the time.



## Power consumption

Power consumption measurements in the tables below are for the MC7330 Mini Card module connected to the host PC via USB.

The module does not have its own power source and depends on the host device for power. For a description of input voltage requirements, see [Power supply on page 30](#).

**Table 5-1: Averaged standby DC power consumption**

Signal	Description	Bands <sup>1</sup>	Current			Notes / configuration
			Typ	Max <sup>2</sup>	Unit	
VCC	Standby current consumption (Sleep mode activated <sup>3</sup> )					
	LTE	LTE Bands	1.8	3.0	mA	DRX cycle = 8 (2.56 s)
	HSDPA / WCDMA	UMTS bands	1.8	3.0	mA	DRX cycle = 8 (2.56 s)
	GSM / GPRS / EDGE	GSM bands	2.4	3.5	mA	MFRM = 5 (1.175 s)
	Standby current consumption <sup>4</sup> (Sleep mode deactivated <sup>3</sup> )					
	LTE	LTE bands	25	30	mA	DRX cycle = 8 (2.56 s)
	HSDPA / WCDMA	UMTS bands	23	28	mA	DRX cycle = 8 (2.56 s)
	GSM / GPRS / EDGE	GSM bands	27	32	mA	MFRM = 5 (1.175 s)
	Low Power Mode (LPM)/Offline Mode <sup>4</sup> (Sleep mode activated <sup>3</sup> )					
	RF disabled, but module is operational		1.3	1.6	mA	
	Low Power Mode (LPM)/Offline Mode <sup>4</sup> (Sleep mode deactivated <sup>3</sup> )					
	RF disabled, but module is operational		23	27	mA	

1. For supported bands, see [Table 4-1, LTE frequency band support](#), on page 45, [Table 4-3, WCDMA frequency band support](#), on page 46, and [Table 4-4, GSM frequency band support](#), on page 46.
2. Measured at 30°C/nominal voltage.
3. Assumes USB bus is fully suspended during measurements
4. LPM and standby power consumption will increase when LEDs are enabled. To reduce power consumption, configure LEDs to remain off while in standby and LPM modes.

**Table 5-2: Averaged call mode DC power consumption**

Description	Current <sup>1</sup>		Notes
	Max <sup>2</sup>	Unit	
LTE	300	mA	<ul style="list-style-type: none"> <li>68/23 Mbps—0 dBm Tx power</li> <li>10 MHz bandwidth</li> <li>MIMO operation</li> </ul>
	600	mA	<ul style="list-style-type: none"> <li>68/23 Mbps—20 dBm Tx power</li> <li>10 MHz bandwidth</li> <li>MIMO operation</li> </ul>
	950 <sup>3</sup>	mA	<ul style="list-style-type: none"> <li>Worst case</li> <li>68/23 Mbps—23 dBm Tx power</li> <li>All bands</li> <li>20 MHz bandwidth</li> </ul>
WCDMA	200	mA	<ul style="list-style-type: none"> <li>384 kbps at 0 dBm Tx power</li> </ul>
	500	mA	<ul style="list-style-type: none"> <li>384 kbps at 20 dBm Tx power</li> </ul>
	850	mA	<ul style="list-style-type: none"> <li>Worst case</li> <li>23 dBm Tx power</li> </ul>
HSPA	250	mA	<ul style="list-style-type: none"> <li>All speeds at 0 dBm Tx power</li> </ul>
	550	mA	<ul style="list-style-type: none"> <li>All speeds at 20 dBm Tx power</li> </ul>
	925	mA	<ul style="list-style-type: none"> <li>Worst case</li> <li>23 dBm Tx power</li> </ul>
GSM/GPRS	525	mA	<ul style="list-style-type: none"> <li>All bands</li> <li>2 timeslots at 32 dBm Tx power</li> </ul>
EDGE	550	mA	<ul style="list-style-type: none"> <li>All bands</li> <li>4 timeslots at 27 dBm Tx power</li> </ul>
Peak current (averaged over 100 $\mu$ s)	2.5	A	<ul style="list-style-type: none"> <li>All GSM/GPRS/EDGE bands</li> </ul>

1. Measured at 30°C/nominal voltage.

2. Highest current is on LTE Band 1.

3. Worst case current at temperature/voltage extremes is 1.1 A.

**Table 5-3: Miscellaneous DC power consumption**

Signal	Description	Current / Voltage			Unit	Notes / configuration
		Min	Typ	Max		
VCC	USB active current		10	15	mA	High speed USB connection, $C_L = 50$ pF on D+ and D- signals
	Inrush current		750	2500	mA	<ul style="list-style-type: none"> <li>Assumes power supply turn on time &gt; 100µs</li> <li>Dependent on host power supply rise time.</li> </ul>
GNSS Signal connector 1	Active bias on GNSS port	50	75	100	mA	GNSS connector 1 in <a href="#">Figure 4-1</a> on page 41
	Max. voltage output @ 75mA			3.3	V	

## Module power states

The module has four power states, as described in [Table 5-4](#).

**Table 5-4: Module power states**

State	Details	Host is powered	Module is powered	USB interface active	RF enabled
<b>Normal (Default state)</b>	<ul style="list-style-type: none"> <li>Module is active</li> <li>Default state when VCC is first applied in the absence of W_DISABLE_N control</li> <li>Module is capable of placing/receiving calls, or establishing data connections on the wireless network</li> <li>Current consumption is affected by several factors, including: <ul style="list-style-type: none"> <li>Radio band being used</li> <li>Transmit power</li> <li>Receive gain settings</li> <li>Data rate</li> <li>Number of active Tx time slots</li> </ul> </li> </ul>	✓	✓	✓	✓
<b>Low power ('Airplane mode')</b>	<ul style="list-style-type: none"> <li>Module is active</li> <li>Module enters this state: <ul style="list-style-type: none"> <li>Under host interface control: <ul style="list-style-type: none"> <li>Host issues AT+CFUN=0 ([1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)), or</li> <li>Host asserts W_DISABLE_N, after AT!PCOFFEN=0 has been issued.</li> </ul> </li> <li>Automatically, when critical temperature or voltage trigger limits have been reached</li> </ul> </li> </ul>	✓	✓	✓	✗

**Table 5-4: Module power states (Continued)**

State	Details	Host is powered	Module is powered	USB interface active	RF enabled
<b>Sleep</b>	<ul style="list-style-type: none"> <li>Normal state of module between calls or data connections</li> <li>Module cycles between wake (polling the network) and sleep, at network provider-determined interval.</li> </ul>	✓	✓	✗	✗
<b>Disconnected</b>	<ul style="list-style-type: none"> <li>Host power source is disconnected from the module and all voltages associated with the module are at 0 V.</li> </ul>	✗	✗	✗	✗

## Power state transitions

The module uses state machines to monitor supply voltage and operating temperature, and notifies the host when critical threshold limits are exceeded. (See [Table 5-5](#) for trigger details and [Figure 5-1](#) for state machine behavior.)

Power state transitions may occur:

- Automatically, when critical supply voltage or module temperature trigger levels are encountered.
- Under host control, using available AT commands in response to user choices (for example, opting to switch to airplane mode) or operating conditions.

**Table 5-5: Power state transitions (including voltage/temperature trigger levels)**

Transition	Voltage		Temperature <sup>1</sup>		Notes
	Trigger	V <sup>2</sup>	Trigger	°C	
Normal to Low Power	<b>VOLT_HI_CRIT</b>	3.8	<b>TEMP_LO_CRIT</b>	-45	<ul style="list-style-type: none"> <li>RF activity suspended</li> </ul>
	<b>VOLT_LO_CRIT</b>	2.9	<b>TEMP_HI_CRIT</b>	110	
Low Power to Normal	<b>VOLT_HI_NORM</b>	3.5	<b>TEMP_NORM_LO</b>	-40	<ul style="list-style-type: none"> <li>RF activity resumed</li> </ul>
Low Power to Normal or Remain in Normal (Remove warnings)	<b>VOLT_LO_NORM</b>	3.05	<b>TEMP_HI_NORM</b>	85	
Normal (Issue warning)	<b>VOLT_LO_WARN</b>	2.95	<b>TEMP_HI_WARN</b>	95	
Power off/on (Host-initiated)	-	-	-	-	<ul style="list-style-type: none"> <li>Power off recommended when supply voltage or module operating temperature is critically low or high.</li> </ul>

1. Module-reported temperatures at the printed circuit board.

2. Supply voltage—3.3V

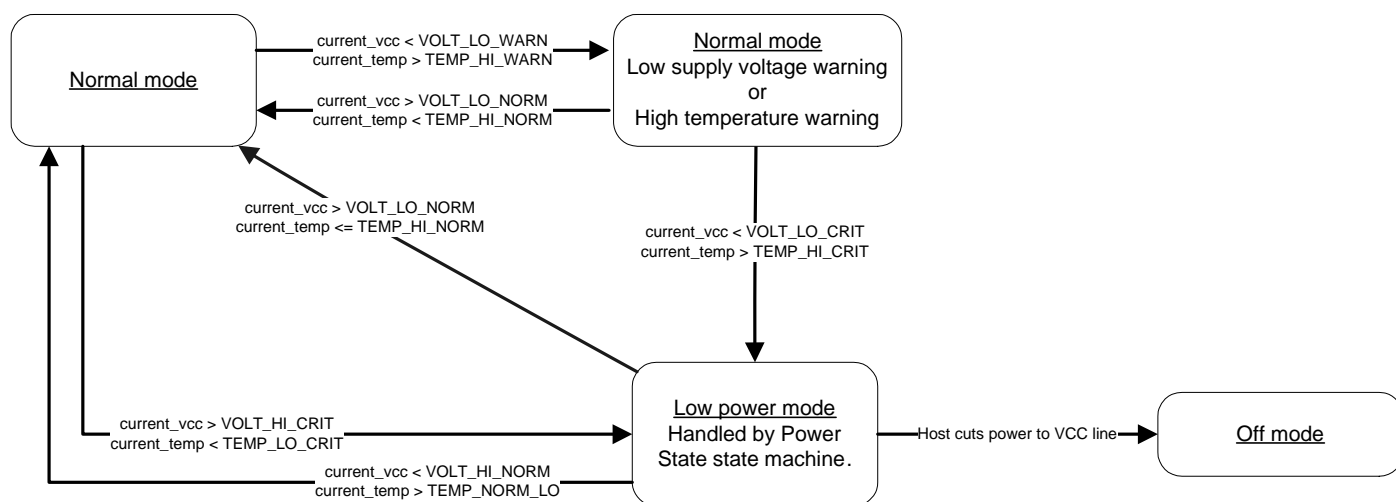


Figure 5-1: Voltage/temperature monitoring state machines

## Power interface

### Power ramp-up

On initial power up, inrush current depends on the power supply rise time—turn on time >100  $\mu$ s is required for < 3A inrush current.

The supply voltage must remain within specified tolerances while this is occurring.

### Power-up timing

Figure 5-2 describes the timing sequence for powering the module on and off.

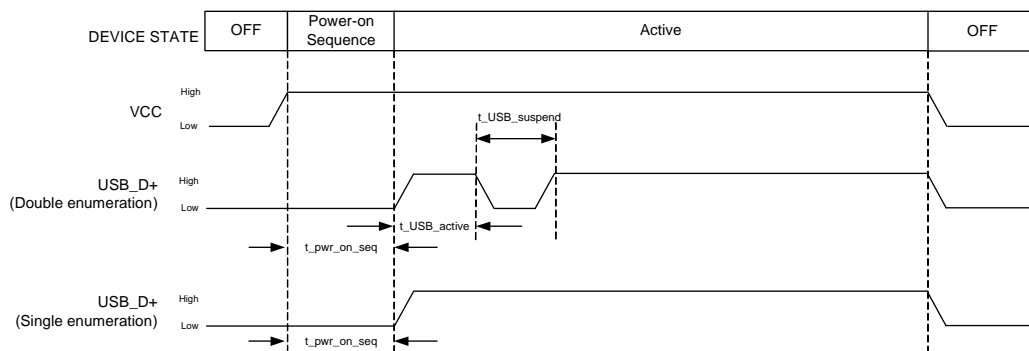


Figure 5-2: Signal timing (Power-on, and USB enumeration)

**Table 5-6: Power-on timing parameters (double enumeration)**

Parameter	Typical (s)	Maximum (s)
t_pwr_on_seq	0.43	0.5
t_USB_active	0.25	0.3
t_USB_suspend	12	13

**Table 5-7: Power-on timing parameters (single enumeration)**

Parameter	Typical (s)	Maximum (s)
t_pwr_on_seq	12	13

## USB enumeration

The unit supports single and double USB enumeration with the host:

- Single enumeration—Enumeration starts within maximum t\_pwr\_on\_seq seconds of power-on.
- Double enumeration—As shown in [Figure 5-2](#):
  - First enumeration starts within t\_pwr\_on\_seq seconds of power-on (while USB\_D+ is high)
  - Second enumeration starts within 14 seconds of power-on (when USB\_D+ goes high again)

## Transmit power waveform (GSM)

As shown in [Figure 5-3](#), at maximum GSM transmit power, the input current can remain at 2.2 A for up to 25% of each 4.6 ms GSM cycle (1.15 ms) after reaching an initial peak of 2.5 A (average over 100  $\mu$ s). For class 12 operation, the peak could remain for 2.3 ms (four timeslots).

The 2.2 A current draw is for 50 ohm systems (1:1 VSWR). For worst-case antenna designs (3.5:1 VSWR), the current draw could increase to 2.5 A, as shown in the diagram.

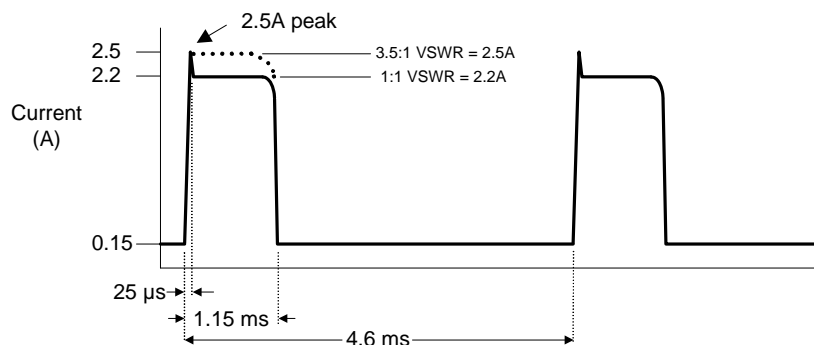


Figure 5-3: GSM transmit power waveform (class 10 operation)



## Power supply noise

Noise in the power supply can lead to noise in the RF signal.

The power supply ripple limit for the module is no more than 200 mVp-p 1 Hz to 100 kHz. This limit includes voltage ripple due to transmitter burst activity.

Additional decoupling capacitors can be added to the main VCC line to filter noise into the device.

## SED (Smart Error Detection)

The module uses a form of SED to track premature modem resets.

- Module tracks consecutive resets occurring soon after power-on.
- After a sixth consecutive reset, the module waits in boot-and-hold mode for a firmware download to resolve the power-cycle problem.

## Tx power control

The module's Tx power limit may be controlled using either SAR backoff AT commands (defined in [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference (Doc# 4114486)*), or the DPR (Dynamic power control) signal. Use the GPIOSENABLE parameter for !CUSTOM to choose the method:

- AT commands:
  - !SARSTATED—Set (or report) the default SAR backoff state that the device uses when it powers up. This setting persists across power cycles and overrides any PRI setting.
  - !SARSTATE—Set (or report) the current SAR backoff state (override the default state). This change in state is non-persistent across power cycles.
  - !SARBACKOFF—Set (or report) the maximum Tx power limit for a specific band/technology/state combination.
- Dynamic power control—The module's firmware monitors DPR (pin 46) and adjusts the RF Tx power appropriately, as detailed in [Table 5-8](#). (This state change is equivalent to using the !SARSTATE AT command.)

*Note: A customization is available to invert the DPR logic. (e.g. DPR low = No SAR backoff)*

**Table 5-8: Dynamic power control of SAR backoff state**

DPR	SAR backoff state
High <sup>1</sup>	No SAR backoff
Low	Backoff 1

1. DPR is pulled high by default.

*Note: The host can implement an open collector drive for the DPR pin (if a 1.8 V-compatible drive is not available.)*



## >> 6: Software Interface

### Support tools

The MC7330 is compatible with the following support tools from Sierra Wireless and authorized third parties:

- Firmware update utilities from Sierra Wireless
- Sierra Wireless Logger
- QXDM from QUALCOMM
- Noise profiling tool
- QUALCOMM Product Support Tool (QPST)
- Windows and Linux SDKs (including API and drivers)

### USB interface

The device supports the Qualcomm QMI interface.

Please contact your Sierra Wireless account representative for QMI interface documentation.

### MTU size (Windows 7)

The MTU (Maximum Transmission Unit) size is configured using a driver installer command line option:

MTUSize=<value> (<value> is the size in bytes)

Example:

driverinstaller /MTUSize=1428

---

*Note: Wireless network operators will have their own specific MTU requirements.*

---





## 7: Mechanical and Environmental Specifications

7

The MC7330 module complies with the mechanical and environmental specifications in [Table 7-1](#). Final product conformance to these specifications depends on the [OEM](#) device implementation.

**Table 7-1: Mechanical and environmental specifications**

	Mode	Details
Temperature	Operational	Class A <sup>1</sup> : -30°C to +70°C (3GPP compliant)  Class A is defined as the operating temperature range within which the device: <ul style="list-style-type: none"><li>• Exhibits normal function during and after environmental exposure.</li><li>• Meets the minimum requirements of 3GPP, 3GPP2, or appropriate wireless standards.</li></ul>
		Class B <sup>1</sup> : -40°C to +85°C (non-3GPP compliant)  Class B is defined as the operating temperature range within which the device: <ul style="list-style-type: none"><li>• Remains functional during and after environmental exposure.</li><li>• Exhibits the ability to establish a voice, SMS or DATA call (emergency call) at all times even when one or more environmental constraints exceed the specified tolerances.</li></ul>
		Internal module temperature: <ul style="list-style-type: none"><li>• Class A—Recommended temperature<sup>2</sup>: &lt; 85°C (3GPP compliant)</li><li>• Class B—Maximum temperature<sup>2</sup>: &lt; 100°C (non-3GPP compliant)</li></ul>
	Non-operational	-40°C to +85°C, 96 hours (from MIL-STD 202 Method 108)
Relative humidity	Operational	65°C, 95% relative humidity for 10 days (non-condensing)
	Non-operational	85°C, 85% relative humidity for 48 hours (non-condensing)
Vibration	Non-operational	Random vibration, 10 to 2000 Hz, 0.1 g <sup>2</sup> /Hz to 0.0005 g <sup>2</sup> /Hz, in each of three mutually perpendicular axes. Test duration of 60 minutes for each axis, for a total test time of three hours.
Shock	Non-operational	Half sine shock, 11 ms, 30 g, 8x each axis. Half sine shock, 6 ms, 100 g, 3x each axis.
Drop	Non-operational	1 m on concrete on each of six faces, two times (module only).

**Table 7-1: Mechanical and environmental specifications (Continued)**

	Mode	Details
(Electrostatic discharge (See <a href="#">Electrostatic discharge (ESD)</a> on page 64.)	Operational	The RF port (antenna launch and RF connector) complies with the IEC 61000-4-2 standard: <ul style="list-style-type: none"><li>Electrostatic Discharge Immunity: Test: Level3</li><li>Contact Discharge: <math>\pm 6</math> kV</li><li>Air Discharge: <math>\pm 8</math> kV</li></ul>
	Non-operational	The host connector Interface complies with the following standard only: <ul style="list-style-type: none"><li>minimum <math>\pm 500</math> V Human Body Model (JESD22-A114-B)</li></ul>
Thermal considerations		See <a href="#">Thermal considerations</a> on page 64.
Form factor		PCI-Express Mini Card shielded with metal and metalized fabric (F2 specification)
Dimensions		Length: 50.95 mm Width: 30 mm Thickness: 2.75 mm (max) Weight: 8.6 g

1. Ambient temperature (temperature around the module). Proper mounting, heat sinks and active cooling may be required, depending on the integrated application.
2. Measured by AT!PCTEMP

## Device views

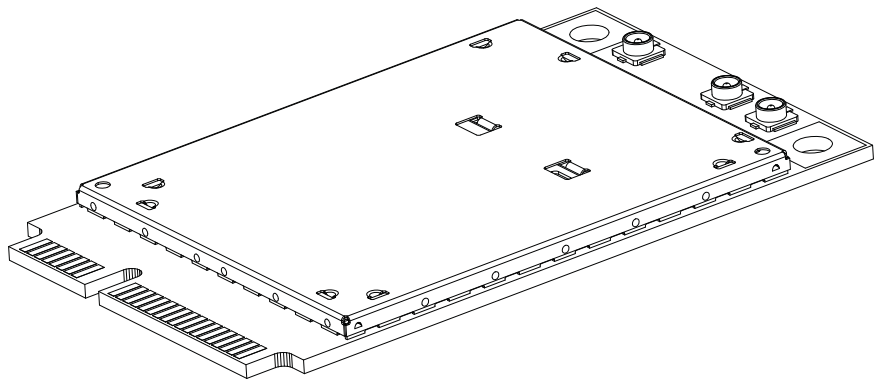


Figure 7-1: Top view

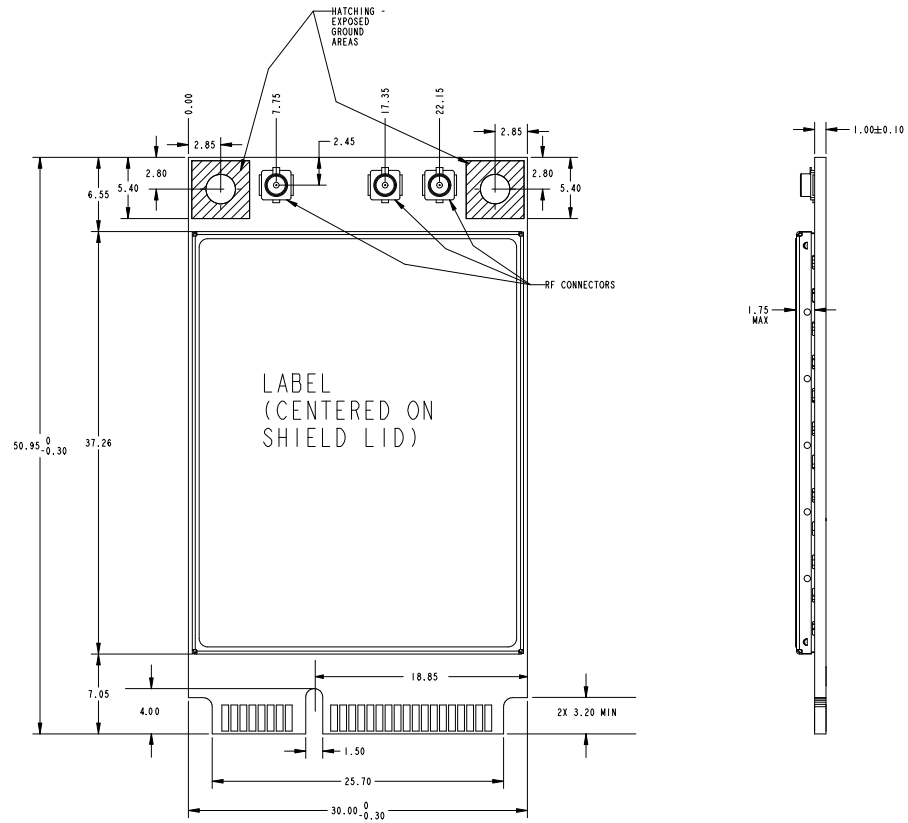


Figure 7-2: Dimensioned view

## Labeling



Figure 7-3: Sample unit label

*Note: The displayed label is an example only. The production label will vary by SKU.*

The MC7330 label is non-removable and contains:

- Sierra Wireless logo and product name

- **IMEI** number in Code-128 barcode format
- **SKU** number (when required)
- Factory Serial Number (**FSN**) in alphanumeric format
- Manufacturing date code (incorporated into FSN)
- Licensed vendor logo
- Applicable certification marks/details (e.g. FCC ID, CE information, etc. Example shows FCC ID.)

---

*Note: The MC7330 supports **OEM** partner-specific label requirements.*

---

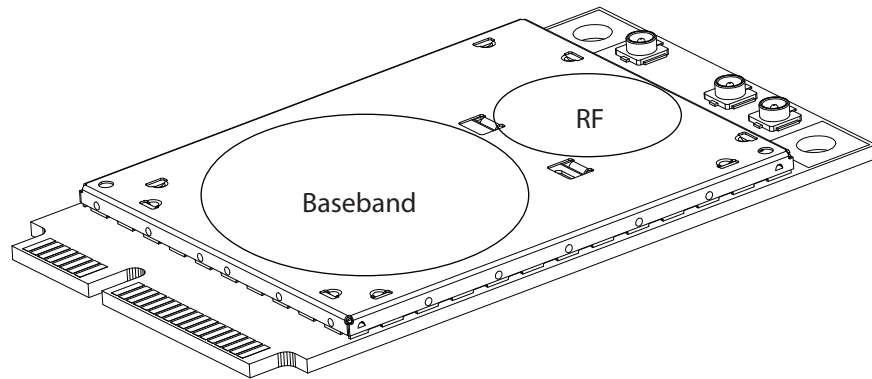
## Electrostatic discharge (ESD)

The OEM is responsible for ensuring that the Mini Card host interface pins are not exposed to ESD during handling or normal operation. (See [Table 7-1 on page 61](#) for specifications.)

ESD protection is highly recommended for the SIM connector at the point where the contacts are exposed, and for any other signals from the host interface that would be subjected to ESD by the user of the product. (The device includes ESD protection on the antenna.)

## Thermal considerations

Embedded modules can generate significant amounts of heat that must be dissipated in the host device for safety and performance reasons.



*Figure 7-4: Shield locations*

The amount of thermal dissipation required depends on:

- Supply voltage—Maximum power dissipation for the module can be up to 3.5 W at voltage supply limits.
- Usage—Typical power dissipation values depend on the location within the host product, throughput, amount of data transferred, etc.



Specific areas requiring heat dissipation are shown in [Figure 7-4](#):

- RF—Top and bottom faces of module near RF connectors. Likely to be the hottest area.
- Baseband—Top and bottom faces of module, below the RF area.

To enhance heat dissipation:

- Maximize airflow over/around the module.
- Locate the module away from other hot components.
- Module mounting holes must be used to attach (ground) the device to the main PCB ground or a metal chassis.
- You may need to add a heat sink that mounts the module to the main PCB (thermal compound or pads must be used between the module and the heat sink).
- You may also need active cooling to pull heat away from the module.

---

*Note: Adequate dissipation of heat is necessary to ensure that the module functions properly.*

---

## Module integration testing

When testing your integration design:

- Test to your worst case operating environment conditions (temperature and voltage)
- Test using worst case operation (transmitter on 100% duty cycle, maximum power)
- Monitor temperature at all shield locations. Attach thermocouples to the areas indicated in [Figure 7-4](#) on page 64 (Baseband, RF).
- Monitor the module's internal temperature using the command **AT!PCTEMP**. (See [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference* (Doc# 4114486).)

---

*Note: Make sure that your system design provides sufficient cooling for the module—proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.*

*The internal module temperature must be kept to <100°C when integrated to prevent damage to the module's components. For best performance, keep the internal module temperature below 85°C.*

---

(For acceptance, certification, quality, and production (including RF) test suggestions, see [Testing on page 75](#).)



## 8: Regulatory Compliance and Industry Certifications

This module is designed to meet, and upon commercial release, will meet the requirements of the following regulatory bodies and regulations, where applicable:

- The National Communications Commission (NCC) of Taiwan, Republic of China
- Ministry of Internal Affairs and Communications (MIC) of Japan

Additional certifications and details on specific country approvals may be obtained upon customer request—contact your Sierra Wireless account representative for details.

Additional testing and certification may be required for the end product with an embedded MC7330 modem and are the responsibility of the [OEM](#). Sierra Wireless offers professional services-based assistance to OEMs with the testing and certification process, if required.

### Important notice

Because of the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless and its affiliates accept no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

### Safety and hazards

Do not operate your MC7330 modem:

- In areas where blasting is in progress
- Where explosive atmospheres may be present including refuelling points, fuel depots, and chemical plants
- Near medical equipment, life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the MC7330 modem **MUST BE POWERED OFF**. Otherwise, the MC7330 modem can transmit signals that could interfere with this equipment.

In an aircraft, the MC7330 modem **MUST BE POWERED OFF**. Otherwise, the MC7330 modem can transmit signals that could interfere with various onboard systems and may be dangerous to the operation of the aircraft or disrupt the cellular network. Use of a cellular phone in an aircraft is illegal in some jurisdictions. Failure to observe this instruction may lead to suspension or denial of cellular telephone services to the offender, or legal action or both.

Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. The MC7330 modem may be used normally at this time.

## >> A: Antenna Specification

This appendix describes recommended electrical performance criteria for main path, diversity path, and GNSS antennas used with AirPrime embedded modules.

The performance specifications described in this section are valid while antennas are mounted in the host device with antenna feed cables routed in their final application configuration.

*Note: Antennas should be designed **before** the industrial design is finished to make sure that the best antennas can be developed.*

**Table A-1: Antenna requirements <sup>a</sup>**

Parameter	Requirements	Comments
<b>Antenna system</b>	External multi-band 2x2 MIMO antenna system (Ant1/Ant2) <sup>b</sup>	If Ant2 includes GNSS, then it must also satisfy requirements in <a href="#">Table A-2 on page 71</a> .
<b>Operating bands — Antenna 1</b>	824–960 MHz	
	1447–1511 MHz	
	1710–1990 MHz	
	2110–2170 MHz	
<b>Operating bands — Antenna 2</b>	869–894 MHz	
	1495–1511 MHz	
	2110–2170 MHz	
<b>VSWR of Ant1 and Ant2</b>	<ul style="list-style-type: none"> <li>&lt; 2:1 (recommended)</li> <li>&lt; 3:1 (worst case)</li> </ul>	On all bands including band edges
<b>Total radiated efficiency of Ant1 and Ant2</b>	> 50% on all bands	<ul style="list-style-type: none"> <li>Measured at the RF connector.</li> <li>Includes mismatch losses, losses in the matching circuit, and antenna losses, excluding cable loss.</li> <li>Sierra Wireless recommends using antenna efficiency as the primary parameter for evaluating the antenna system.</li> </ul> <p>Peak gain is not a good indication of antenna performance when integrated with a host device (the antenna does not provide omni-directional gain patterns). Peak gain can be affected by antenna size, location, design type, etc.—the antenna gain patterns remain fixed unless one or more of these parameters change.</p>

**Table A-1: Antenna requirements (Continued)<sup>a</sup>**

Parameter	Requirements	Comments
<b>Radiation patterns of Ant1 and Ant2</b>	Nominally Omni-directional radiation pattern in azimuth plane.	
<b>Envelope correlation coefficient between Ant1 and Ant2</b>	<ul style="list-style-type: none"> <li>&lt; 0.4 on 869–894 MHz band</li> <li>&lt; 0.3 on 1495–1511 MHz band</li> <li>&lt; 0.2 on 2110–2170 MHz band</li> </ul>	
<b>Mean Effective Gain of Ant1 and Ant2 (MEG1, MEG2)</b>	≥ -3 dBi	
<b>Ant1 and Ant2 Mean Effective Gain Imbalance I MEG1 / MEG2 I</b>	< 2 dB for MIMO operation < 6 dB for diversity operation	
<b>Maximum antenna gain</b>	Must not exceed antenna gains due to RF exposure and ERP/EIRP limits.	
<b>Isolation between Ant1 and Ant2 (S21)</b>	> 10 dB	<ul style="list-style-type: none"> <li>If antennas can be moved, test all positions for both antennas.</li> <li>Make sure all other wireless devices (Bluetooth or WLAN antennas, etc.) are turned OFF to avoid interference.</li> </ul>
<b>Power handling</b>	<ul style="list-style-type: none"> <li>&gt; 2 W RF power on low bands</li> <li>&gt; 1 W on high bands</li> </ul>	<ul style="list-style-type: none"> <li>Measure power endurance over 4 hours (estimated talk time) using a 2 W CW signal—set the CW test signal frequency to the middle of the PCS Tx band (1880 MHz for PCS).</li> <li>Visually inspect device to ensure there is no damage to the antenna structure and matching components.</li> <li>VSWR/TIS/TRP measurements taken before and after this test must show similar results.</li> </ul>

- a. These worst-case VSWR figures for the transmitter bands may not guarantee RSE levels to be within regulatory limits. The device alone meets all regulatory emissions limits when tested into a cabled (conducted) 50 ohm system. With antenna designs with up to 2.5:1 VSWR or worse, the radiated emissions could exceed limits. The antenna system may need to be tuned in order to meet the RSE limits as the complex match between the module and antenna can cause unwanted levels of emissions. Tuning may include antenna pattern changes, phase/delay adjustment, passive component matching. Examples of the application test limits would be included in FCC Part 22, Part 24 and Part 27, test case 4.2.16 for GSM (ETSI EN 301 511), and test case 4.2.2 for WCDMA (ETSI EN 301 908-1), where applicable.
- b. Ant1—Primary, Ant2—Secondary (Diversity/MIMO/GNSS connector 2)

## Recommended GNSS antenna specifications

**Table A-2: GNSS standalone antenna requirements**

Parameter	Requirements	Comments
<b>Frequency range</b>	<ul style="list-style-type: none"> <li>Narrow-band GPS: 1575.42 MHz <math>\pm</math>2 MHz minimum</li> <li>Wide-band GPS and GLONASS: 1565–1606 MHz recommended</li> </ul>	
<b>Field of view (FOV)</b>	<ul style="list-style-type: none"> <li>Omni-directional in azimuth</li> <li>-45° to +90° in elevation</li> </ul>	
<b>Polarization (average Gv/Gh)</b>	> 0 dB	Vertical linear polarization is sufficient.
<b>Free space average gain (Gv+Gh) over FOV</b>	> -6 dBi (preferably > -3 dBi)	Gv and Gh are measured and averaged over -45° to +90° in elevation, and $\pm$ 180° in azimuth.
<b>Gain</b>	<ul style="list-style-type: none"> <li>Maximum gain and uniform coverage in the high elevation angle and zenith.</li> <li>Gain in azimuth plane is not desired.</li> </ul>	
<b>Average 3D gain</b>	> -5 dBi	
<b>Isolation between GNSS and Ant1</b>	> 10 dB in all uplink bands	
<b>Typical VSWR</b>	< 2.5:1	
<b>Polarization</b>	Any other than LHCP (left-hand circular polarized) is acceptable.	

## Antenna tests

The following guidelines apply to the requirements described in [Table A-1 on page 69](#) and [Table A-2 on page 71](#):

- Perform electrical measurements at room temperature (+20°C to +26°C) unless otherwise specified
- For main and diversity path antennas, make sure the antennas (including contact device, coaxial cable, connectors, and matching circuit with no more than six components, if required) have nominal impedances of 50  $\Omega$  across supported frequency bands.
- All tests (except isolation/correlation coefficient)—Test the main or diversity antenna with the other antenna terminated.

- Any metallic part of the antenna system that is exposed to the outside environment needs to meet the electrostatic discharge tests per IEC61000-4-2 (conducted discharge +8kV).
- The functional requirements of the antenna system are tested and verified while the embedded module's antenna is integrated in the host device.

---

*Note: Additional testing, including active performance tests, mechanical, and accelerated life tests can be discussed with Sierra Wireless' engineering services. Contact your Sierra Wireless representative for assistance.*

---



## >> B: Design Checklist

## B

This chapter provides a summary of the design considerations mentioned throughout this guide. This includes items relating to the power interface, RF integration, thermal considerations, cabling issues, and so on.

*Note: This is NOT an exhaustive list of design considerations. It is expected that you will employ good design practices and engineering principles in your integration.*

**Table B-1: Hardware integration design considerations**

Suggestion	Section where discussed
<b>Component placement</b>	
Protect the SIM socket so the SIM cannot be removed while the host is powered up.	<a href="#">SIM implementation on page 33</a>
If an ESD suppressor is not used, allow space on the SIM connector for series resistors in layout. (Up to 100 $\Omega$ may be used depending on ESD testing requirements).	<a href="#">SIM implementation on page 33</a>
Minimize RF cable losses as these affect performance values listed in product specification documents.	<a href="#">RF connections on page 41</a>
<b>Antennas</b>	
Match the module/antenna coax connections to 50 $\Omega$ —mismatched antenna impedance and cable loss negatively affect RF performance.	<a href="#">RF connections on page 41</a>
If installing CDMA and UMTS modules in the same device, consider using separate antennas for maximum performance.	<a href="#">Antenna and cabling on page 42</a>
<b>Power</b>	
Make sure the power supply can handle the maximum current specified for the module type.	<a href="#">Power consumption on page 51</a>
Limit the total impedance of VCC and GND connections to the SIM at the connector to less than 1 $\Omega$ (including any trace impedance and lumped element components—inductors, filters, etc.). All other lines must have a trace impedance less than 2 $\Omega$ .	<a href="#">SIM implementation on page 33</a>
Decouple the VCC line close to the SIM socket. The longer the trace length (impedance) from socket to module, the greater the capacitance requirement to meet compliance tests.	<a href="#">SIM implementation on page 33</a>
<b>EMI/ESD</b>	
Investigate sources of localized interference early in the design cycle.	<a href="#">Methods to mitigate decreased Rx performance on page 44</a>
Provide ESD protection for the SIM connector at the exposed contact point (in particular, the CLK, VCC, IO, and RESET lines).	<a href="#">SIM implementation on page 33</a>

**Table B-1: Hardware integration design considerations (Continued)**

<b>Suggestion</b>	<b>Section where discussed</b>
Keep very low capacitance traces on the USIM_DATA and USIM_CLK signals.	<a href="#">SIM implementation on page 33</a>
To minimize noise leakage, establish a very good ground connection between the module and host.	<a href="#">Ground connection on page 43</a>
Route cables away from noise sources (for example, power supplies, LCD assemblies, etc.).	<a href="#">Methods to mitigate decreased Rx performance on page 44</a>
Shield high RF-emitting components of the host device (for example, main processor, parallel bus, etc.).	<a href="#">Methods to mitigate decreased Rx performance on page 44</a>
Use discrete filtering on low frequency lines to filter out unwanted high-order harmonic energy.	<a href="#">Methods to mitigate decreased Rx performance on page 44</a>
Use multi-layer PCBs to form shielding layers around high-speed clock traces.	<a href="#">Methods to mitigate decreased Rx performance on page 44</a>
<b>Thermal</b>	
Test to worst case operating conditions—temperature, voltage, and operation mode (transmitter on 100% duty cycle, maximum power).	<a href="#">Thermal considerations on page 64</a>
Use appropriate techniques to reduce module temperatures (for example, airflow, heat sinks, heat-relief tape, module placement, etc.).	<a href="#">Thermal considerations on page 64</a>
<b>Host/Modem communication</b>	
Make sure the host USB driver supports remote wakeup, resume, and suspend operations, and serial port emulation.	<i>[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)</i>
When no valid data is being sent, do not send SOF tokens from the host (causes unnecessary power consumption).	<i>[4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)</i>

---

*Note: All AirPrime embedded modules are factory-tested to ensure they conform to published product specifications.*

---

Developers of OEM devices integrating Sierra Wireless AirPrime embedded modules should include a series of test phases in their manufacturing process to make sure that *their* devices work properly with the embedded modules.

Suggested phases include:

- [Acceptance testing](#)—Testing of modules when they are received from Sierra Wireless
- [Certification testing](#)—Testing of completed devices to obtain required certifications before beginning mass production
- [Production testing](#)—Testing of completed devices with the modules embedded
- [Quality assurance testing](#)—Post-production

## AT command entry timing requirement

Some AT commands require time to process before additional commands are entered. For example, the modem will return “OK” when it receives **ATIDAFTMACT**. However, if **ATIDASBAND** is received too soon after this, the modem will return an error.

When building automated test scripts, ensure that sufficient delays are embedded where necessary to avoid these errors.

## Acceptance testing

---

*Note: Acceptance testing is typically performed for **each** shipment received.*

---

When you receive a shipment from Sierra Wireless, you should make sure it is suitable before beginning production.

From a random sampling of units, test that:

- Units are operational
- Units are loaded with the correct firmware version

## Acceptance test requirements

To perform the suggested tests, you require a test system in which to temporarily install the module, and you must be able to observe the test device's LED indicator.

## Acceptance test procedure

The following is a suggested acceptance testing procedure using Sierra Wireless' Skylight™ (formerly Watcher™) software:

---

*Note: You can perform these tests using appropriate AT commands.*

---

### Test 1: Check power-up and initialization

1. After installing the module, start the test system.
2. Launch Skylight.
3. Check the LED—If the LED is off, there is a problem with the module or with the connection to the LED.

### Test 2: Check version numbers

1. From Skylight, select **Help > About**.
2. Verify that the firmware version in the **About** window is correct.
3. Close the **About** window.

If the module fails either of these tests, or is not recognized by Skylight:

1. Replace the module with one that is known to work correctly and repeat the tests.
2. If the tests are successful, reinstall the original module and repeat the tests.

If the module still does not work correctly, contact your account manager.

## Certification testing

---

*Note: Typically, certification testing of your device with the integrated module is required one time only.*

---

The AirPrime embedded module has been certified as described in [Regulatory Compliance and Industry Certifications on page 67](#).

When you produce a host device with a Sierra Wireless AirPrime embedded module, you must obtain certifications for the final product from appropriate regulatory bodies in the jurisdictions where it will be distributed.

The following are *some* of the regulatory bodies from which you may require certification—it is your responsibility to make sure that you obtain all necessary certifications for your product from these or other groups:

- FCC (Federal Communications Commission—[www.fcc.gov](http://www.fcc.gov))
- Industry Canada ([www.ic.gc.ca](http://www.ic.gc.ca))

- GCF (Global Certification Forum—[www.globalcertificationforum.org](http://www.globalcertificationforum.org)) outside of North America
- PTCRB (PCS Type Certification Review Board—[www.ptcrb.com](http://www.ptcrb.com)) in North America

## Production testing

---

*Note: Production testing typically continues for the life of the product.*

---

Production testing ensures that, for each assembled device, the module is installed correctly (I/O signals are passed between the host and module), and the antenna is connected and performing to specifications (RF tests).

Typical items to test include:

- Host connectivity
- Baseband (host/module connectors)
- RF assembly (Tx and/or Rx, as appropriate)
- Network availability
- Host/device configuration issues

---

*Note: The amount and types of tests to perform are **your** decision—the tests listed in this section are guidelines only. Make sure that the tests you perform exercise functionality to the degree that **your** situation requires.*

---

Use an appropriate test station for your testing environment (see [Acceptance test requirements on page 76](#) for suggestions) and use AT commands to control the integrated module.

---

*Note: Your test location must be protected from ESD to avoid interference with the module and antenna(s), assuming that your test computer is in a disassembled state. Also, consider using an RF shielding box—local government regulations may prohibit unauthorized transmissions.*

---

## Functional production test

This section presents a suggested procedure for performing a basic manual functional test on a laboratory bench using an AirPrime embedded module and a Mini Card Dev Kit. When you have become familiar with the testing method, use it to develop your own automated production testing procedures.

### Suggested production tests

Consider the following tests when you design your production test procedures for devices with the AirPrime module installed.

- Visual check of the module's connectors and RF assemblies
- Module is operational

- USB connection is functional
- LED is functional
- W\_DISABLE\_N (enter low power mode)
- Firmware revision check
- Rx tests on main and auxiliary paths
- Tx test

## Production test procedure

The following is a suggested test plan—you must decide which tests are appropriate for your product. You may wish to add additional tests that more fully exercise the capabilities of your product.

Using an appropriate Dev Kit-based test station, and referring to the appropriate AT command references:

1. Visually inspect the module's connectors and RF assemblies for obvious defects before installing it in the test station.
2. Ensure that the module is powered off (no voltage on VCC).
3. If using Linux, determine if any USB devices are currently connected to the computer:
  - a. Open a shell window and enter the command `ls /dev/tty/USB*`.
  - b. Record the `ttyUSBn` values that are returned; these are the currently connected USB devices. If the command returns “no such file or directory”, there are no devices currently connected.
4. Provide power to the module (voltage on VCC).
5. Test W\_DISABLE\_N.
6. Test USB functionality—Check for USB enumeration.
  - (Windows systems) The Device Manager shows the device under Network adapters. For example:



- (Linux systems) Enter the command `ls /dev/tty/USB*` and then record and compare the results with those from [Step 3](#). If there are any new `ttyUSBn` devices, then the modem has enumerated successfully. (The AT port is the *last* new device.)
7. Make sure your modem is connected and running, and then establish contact with the module:
    - **Windows systems:** Use a terminal emulation/communications program such as Microsoft HyperTerminal® to connect to the Sierra Wireless modem (see listings in [Step 6](#)):
      - a. Start HyperTerminal.

- b. Select **File > Connection Description**. The Connection Description dialog box appears.
  - i. Type Sierra in the Name box and click **OK**. The Connect To dialog box appears.
  - ii. Click **OK** without changing any of the displayed information. The Connect dialog box appears.
  - iii. Click **Cancel**.
  - iv. Type **ATZ** in the HyperTerminal window. If the connection is established, the message OK appears.
- **Linux systems:** Use a terminal emulation/communications program such as minicom to connect over the device handle for AT commands (see listings in [Step 6](#)):

---

*Note: If necessary, use **ATE1** to enable echo.*

---



---

*Note: If the command “minicom” is not found, then use a different program, or download minicom and repeat this step. See [Downloading and configuring minicom for Linux systems on page 80](#) for details.*

---

- i. Start minicom:
  - First use of the modem: From the command line, type minicom -s. (The ‘-s’ switch shows the configuration menu.)
  - Subsequent uses: From the command line, type minicom. (The ‘-s’ switch is assumed.)

The minicom configuration details appear and the message OK appears when the connection is established.

```

cn Telnet 00.0.00.00
Welcome to minicom 2.2
OPTIONS: I18n
Compiled on Apr 27 2007, 15:50:20.
Port /dev/ttyUSB2

Press CTRL-A Z for help on special keys

AT S7=45 S0=0 L1 U1 X4 &c1 E1 Q0
OK
CTRL-A Z for help !115200 8N1 ! NOR ! Minicom 2.2 ! UT102 ! Offline
  
```

8. Display the firmware version:
  - **ATI**
9. Test the LED—Set the LED in blinking mode using this command, then visually verify that the LED turns off and on:
  - **AT!LDTEST=0,0** (LED on)
  - **AT!LDTEST=0,1** (LED off)
10. Unlock the extended AT command set:
  - **AT!ENTERCND**
11. Put the module in diagnostic/factory test mode:
  - **AT!DAFTMACT**
12. Communicate with the SIM using **+CPIN** or **+CIMI**.  
When performing RF tests, use a test platform as described in [Suggested testing equipment on page 87](#).
13. Test RF transmission, if desired:
  - (UMTS) See [UMTS \(WCDMA/GSM\) RF transmission path test on page 80](#).
  - (LTE) To test the LTE transmission path, use a call box.
14. Test RF reception, if desired:
  - (UMTS) See [UMTS \(WCDMA/GSM\) RF receive path test on page 82](#).
  - (LTE) See [LTE RF receive path test on page 84](#).

15. Test standalone GNSS functionality—See [GNSS RF receive path test on page 86](#).

### Downloading and configuring minicom for Linux systems

*Note: This procedure is for Ubuntu systems. If you are using a different Linux distribution, use the appropriate commands for your system to download minicom.*

To download and configure minicom in a Ubuntu system:

*Note: To install minicom, you must have root access, or be included in the sudoers list.*

1. Download and install minicom—enter the following command:  
`sudo apt-get install minicom`
2. When prompted, enter your user password to begin the download and installation. When minicom is installed, the shell prompt appears.
3. Configure minicom to communicate with your modem:
  - a. Start minicom with the following command:  
`minicom -s`
4. Use the down-arrow key to select the **Serial port setup** option.
5. Refer to [Step 6](#) on page 78 to identify the device file handle (/dev/ttyUSBn) used for AT commands.
6. Indicate the file handle to use for AT commands—Enter A and then replace the serial device string with the AT file handle.
7. Press **Enter** twice.
8. Use the down-arrow key to select **Save setup as dfi**.
9. Select **Exit**.

### UMTS (WCDMA/GSM) RF transmission path test

*Note: This procedure segment is performed in [Step 13](#) of the [Production test procedure on page 78](#).*

The suggested test procedure that follows uses the parameters in [Table C-1](#).

**Table C-1: Test settings—UMTS transmission path**

Mode	Test category	850 MHz	900 MHz	1800 MHz	1900 MHz	2100 MHz
WCDMA	Band #	B5	n/a	n/a	n/a	B1
	Band ID	22				9
	Tx Channel <sup>a</sup>	4182				9750



**Table C-1: Test settings — UMTS transmission path (Continued)**

Mode	Test category	850 MHz	900 MHz	1800 MHz	1900 MHz	2100 MHz
GSM	Band #	GSM850	EGSM900	DCS1800	PCS1900	n/a
	Band ID	18	10	11	12	
	Tx Channel <sup>a</sup>	190	65	697	661	

a. Channel values shown are at the center of the corresponding bands.

To test the DUT's transmitter path:

1. Set up the power meter:



- a. Make sure the meter has been given sufficient time to warm up, if necessary, to enable it to take accurate measurements.
- b. Zero-calibrate the meter.
- c. Enable MAP mode.
2. Prepare the DUT using the following AT commands:
  - a. `AT+ENTERCND=<password>` (Unlock extended AT command set.)
  - b. `AT+IDAFTMACT` (Enter test mode.)
  - c. `AT+IDASBAND=<bandValue>` (Set frequency band.)
    - See [Table C-1 on page 80](#) for appropriate <bandValue> values
  - d. `AT+IDASCHAN=<channel>` (Set modem channel)
    - See [Table C-1 on page 80](#) for appropriate <channel> values
  - e. (GSM mode only)
    - `AT+IDAGSTXFRAME=0, 1, 3000, 0` (Set Tx frame structure.)
  - f. `AT+IDASTXON` (Turns on the transmit path.)
  - g. (WCDMA mode only)
    - `AT+IDAWSTXCW=0` (Use a modulated carrier.)
    - `AT+IDASPDM=2, 75` (Set the power level. Repeat command with different offsets until desired Tx power is obtained.)
    - `AT+IDAWSPARANGE=3` (Set to high PA gain state.)
  - h. Offset the tracking (If necessary, repeat with different offsets until the desired frequency is obtained.)
    - (WCDMA mode) `AT+IDASPDM=4, 35100`
    - (GSM mode) `AT+IDASPDM=0, 2240`
  - i. Take the measurement.

*Note: This procedure describes steps using the "Power Meter: Gigatronics 8651A" (with Option 12 and Power Sensor 80701A).*

j. **ATIDASTXOFF** (Turn off the transmitter.)

3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal output power value.
  - Apply a tolerance of  $\pm 5$  to 6 dB to each measurement (assuming a good setup design).
  - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.
  - For GSM mode, the transmit signal is bursted, so the transmit power will appear averaged on the power meter reading.

*Note: The module has a nominal output power of +23 dBm  $\pm 1$  dB in WCDMA mode. However, the value measured by the power meter is significantly influenced (beyond the stated  $\pm 1$  dB output power tolerance) by the test setup (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).*

*Note: When doing the same test over the air in an RF chamber, values are likely to be significantly lower.*

## UMTS (WCDMA/GSM) RF receive path test

*Note: This procedure segment is performed in [Step 14](#) of the [Production test procedure on page 78](#).*

The suggested test procedure that follows uses the parameters in [Table C-2](#).

**Table C-2: Test settings—UMTS receive path**

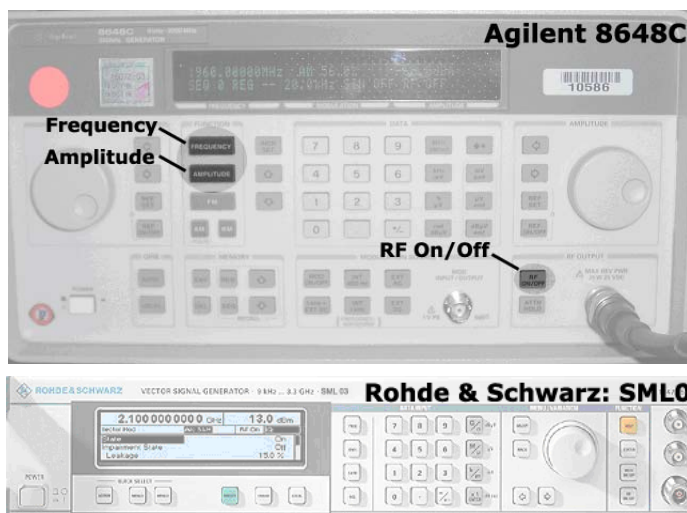
Mode	Test category	850 MHz	900 MHz	1800 MHz	1900 MHz	2100 MHz
WCDMA	Band #	B5	n/a	n/a	n/a	B1
	Frequency <sup>a</sup> (MHz)	882.6				2141.2
	Band ID	22				9
	Rx Channel <sup>b</sup>	4182				9750
GSM	Band #	GSM850	GSM900	DCS1800	PCS1900	n/a
	Frequency <sup>c</sup> (MHz)	881.667	948.067	1842.267	1960.067	
	Band ID	18	10	11	12	
	Rx Channel <sup>c</sup>	190	65	697	661	

- a. Receive frequencies shown are +1.2 MHz offset from center.
- b. Channel values shown are at the center of the corresponding bands.
- c. Receive frequencies shown are +0.067 MHz offset from center.

*Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only.*

To test the DUT's receive path:

1. Set up the signal generator:



- a. Set the amplitude to:
    - -80 dBm (WCDMA mode)
    - -60 dBm (GSM mode)
  - b. Set the frequency for the band being tested. See [Table C-2 on page 82](#) for frequency values.
2. Set up the DUT:
- a. AT!ENTERCND (Unlock extended AT command set.)
  - b. AT!DAFTMACT (Put modem into factory test mode.)
  - c. AT!DASBAND=<band> (Set frequency band.)
    - See [Table C-2 on page 82](#) for <band> values
  - d. AT!DASCHAN=<channel> (Set modem channel)
    - See [Table C-2 on page 82](#) for <channel> values
  - e. AT!DASLNAGAIN=0 (Set the LNA to maximum gain.)
  - f. (WCDMA mode)
    - i. AT!DAWGAVGAGC=9400,0 (For PCS1900, channel 9400 as an example.)
 (GSM mode)
    - ii. AT!DAGSRXBURST=0 (Set to receive burst mode.)
    - iii. AT!DAGGAVGRSSI=190,0 (For channel 190, for example.)
 The returned value is the RSSI in dBm.
3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
- Apply a tolerance of  $\pm 5$  to 6 dB to each measurement (assuming a good setup design).
  - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
  - The Signal Generator power level can be adjusted and new limits found if the radiated test needs greater signal strength.

- Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

*Note: The value measured from the DUT is significantly influenced by the test setup and DUT design (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).*

*Note: Diversity is not available in GSM mode.*

*Note: Setup of the DUT is the same as in [Step 2](#), except for a change to AT!DAWGAVGAGC and the addition of AT!DAWSSCHAIN.*

#### 4. Test diversity paths:

- a. Set up the signal generator as in [Step 1](#).
- b. Set up the DUT:
  - i. AT!ENTERCND (Unlock extended AT command set.)
  - ii. AT!DAFTMACT (Put modem into factory test mode.)
  - iii. AT!DASBAND=<band> (Set frequency band.)
    - See [Table C-2 on page 82](#) for <band> values
  - iv. AT!DAWSSCHAIN=1 (Enable the secondary chain.)
  - v. AT!DASCHAN=<channel> (Set modem channel)
    - See [Table C-2 on page 82](#) for <channel> values
  - vi. AT!DASLNAGAIN=0 (Set the LNA to maximum gain.)
  - vii. AT!DAWGAVGAGC=9400,0,1 (The '1' indicates the diversity path is used.)
- c. Test the limits as in [Step 3](#).

## LTE RF receive path test

*Note: This procedure segment is performed in [Step 14](#) of the [Production test procedure on page 78](#).*

The suggested test procedure that follows uses the parameters in [Table C-3](#) contains parameters used in the suggested test procedure that follows.

**Table C-3: Test settings—LTE receive path**

Mode	Test category	850 MHz	1500 MHz	2100 MHz
LTE	Band #	B19	B21	B1
	Frequency <sup>a</sup> (MHz)	884.5	1505.4	2142.0
	Band ID	55	57	34
	Rx Channel <sup>b</sup>	24075	24525	18300

a. Receive frequencies shown are +2 MHz offset from center

b. Channel values shown are at the center of the corresponding bands.

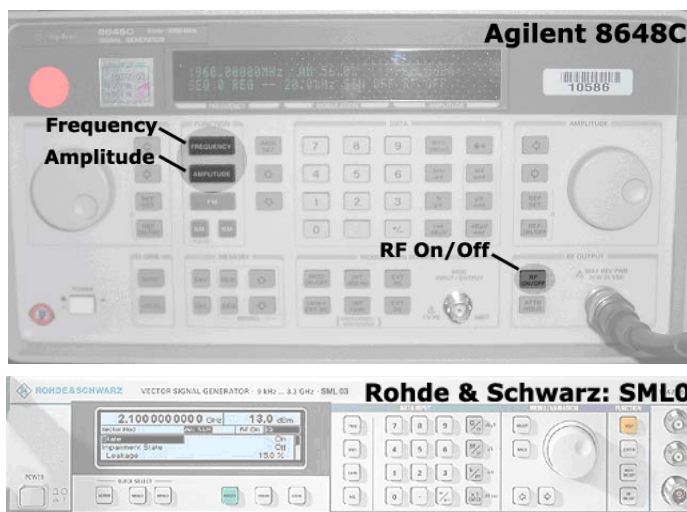
---

*Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only.*

---

To test the DUT's receive path (or diversity path, while connected to the diversity antenna):

1. Set up the signal generator:



- a. Set the amplitude to -70 dBm
  - b. Set the frequency for the band being tested. See [Table C-3 on page 84](#) for frequency values.
2. Set up the DUT:
- a. AT!ENTERCND (Unlock extended AT command set.)
  - b. AT!DAFTMACT (Put modem into factory test mode.)
  - c. AT!DASBAND=<band> (Set frequency band.)
    - See [Table C-3 on page 84](#) for <band> values
  - d. AT!DALSTXBW=<bw> (Set Tx bandwidth.)
  - e. AT!DALSRXBW=<bw> (Set Rx bandwidth.)
  - f. AT!DASCHAN=<channel> (Set modem channel.)
    - See [Table C-3 on page 84](#) for <channel> values
  - g. AT!DALGAVGAGC=<channel>,0 (Get averaged Rx AGC.)
    - See [Table C-3 on page 84](#) for <channel> values
3. Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
- Apply a tolerance of  $\pm 5$  to 6 dB to each measurement (assuming a good setup design).
  - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
  - The Signal Generator power level can be adjusted and new limits found if the radiated test needs greater signal strength.
  - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

---

*Note: The value measured from the DUT is significantly influenced by the test setup and DUT design (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).*

---

## GNSS RF receive path test

The GNSS receive path uses either the dedicated GNSS connector or the shared Diversity/MIMO/GNSS connector.

To test the GNSS receive path:

1. Inject a carrier signal at -110dBm, frequency 1575.52 MHz into the GNSS Rx path at the connector. (Note that this frequency is 100 kHz higher than the actual GPS L1 center frequency.)
2. Test the signal carrier-to-noise level at the GNSS receiver:
  - a. **AT+ENTERCND** (Unlock extended AT command set.)
  - b. **AT+IDAFTMACT** (Put modem into factory test mode.)
  - c. **AT+IDACGPSTESTMODE=1** (Start CGPS diagnostic task.)
  - d. **AT+IDACGPSSTANDALONE=1** (Enter standalone RF mode.)
  - e. **AT+IDACGPSMASKON** (Enable log mask.)
  - f. **AT+IDACGPSCTON** (Return signal-to-noise and frequency measurements.)
  - g. Repeat **AT+IDACGPSCTON** five to ten times to ensure the measurements are repeatable and stable.
3. Leave the RF connection to the Mini Card device intact, and turn off the signal generator.
4. Take several more **IDACGPSCTON** readings. This will demonstrate a 'bad' signal in order to set limits for testing, if needed. This frequency offset should fall outside of the guidelines in the note below, which indicates that the CtoN result is invalid.
5. (Optional) Turn the signal generator on again, and reduce the level to -120dBm. Take more **IDACGPSCTON** readings and use these as a reference for what a marginal/poor signal would be.

---

*Note: The response to **AT+IDACGPSCTON** for a good connection should show CtoN within 58 +/- 5dB and Freq (frequency offset) within 100000 Hz +/- 5000 Hz .*

---

## Quality assurance testing

---

*Note: QA is an ongoing process based on random samples from a finished batch of devices.*

---

The quality assurance tests that you perform on your finished products should be designed to verify the performance and quality of your devices.

The following are *some* testing suggestions that can confirm that the antenna is interfaced properly, and that the RF module is calibrated and performs to specifications:

- Module registration on cellular networks
- Power consumption
- Originate and terminate data and voice (if applicable) calls
- Cell hand-off
- Transmitter and receiver tests
- FER (Frame Error Rate) as an indicator of receiver sensitivity/performance

- Channel and average power measurements to verify that the device is transmitting within product specifications
- RF sensitivity testing—BER/BLER for different bands and modes
- Transmitter and receiver tests (based on relevant sections of the 3GPP TS51010 and 3GPP 34121 documents)

## Suggested testing equipment

To perform production and post-production tests, you will require appropriate testing equipment. A test computer can be used to coordinate testing between the integrated module (on the development kit or host) and the measurement equipment, usually with GPIB connections. The suggested setup includes a power meter to test RF output power and a signal generator to evaluate the receiver.

## Testing assistance provided by Sierra Wireless

Extended AT commands have been implemented to assist with performing FTA GCF tests and portions of CE Mark tests requiring radio module access. These are documented in the [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference (Doc# 4114486)*.

Sierra Wireless offers optional professional services based assistance to [OEMs](#) with regulatory approvals.

## IOT/Operator testing

Interoperability and Operator/Carrier testing of the finished system is the responsibility of the [OEM](#). The test process will be determined with the chosen network operator(s) and will be dependent upon your business relationship with them, as well as the product's application and sales channel strategy.

Sierra Wireless offers assistance to OEMs with the testing process, if required.



## Extended AT commands for testing

Sierra Wireless provides the [2] *AirPrime MiniCard MC73xx/MC8805 AT Command Reference (Doc# 4114486)*, which describes proprietary AT commands that may help in hardware integration design and testing (these commands are NOT intended for use by end users).

Some commands from this document that may be useful for hardware integration are listed in [Table C-4 on page 88](#).

**Table C-4: Extended AT commands**

Command	Description
<b>Password commands</b>	
<b>!ENTERCND</b>	Enable access to password-protected commands
<b>!SETCND</b>	Set AT command password
<b>Modem reset and status commands</b>	
<b>!GRESET</b>	Reset the modem
<b>!GSTATUS</b>	Return the operation status of the modem (mode, band, channel, and so on)
<b>Diagnostic commands</b>	
<b>!BAND</b>	Select a set of frequency bands or reports current selection
<b>!GBAND</b>	Read/set the current operating band
<b>Test commands</b>	
<b>!DAFTMACT</b>	Put the modem into FTM (Factory Test Mode)
<b>!DAFTMDEACT</b>	Put the modem into online mode
<b>!DAGGRSSI</b>	Return the RSSI (Received Signal Strength Indicator) in dBm (GSM mode)
<b>!DAGGAVGRSSI</b>	Return an averaged RSSI (Received Signal Strength Indicator) in dBm (GSM mode)
<b>!DAGGRSSIRAW</b>	Return the raw RSSI (GSM mode)
<b>!DAGINFO</b>	Return GSM mode RF information
<b>!DAGSLOCK</b>	Return the RF synthesizer lock state
<b>!DAGSRXBURST</b>	Set the GSM receiver to burst mode
<b>!DAGSRXCONT</b>	Set the GSM receiver continually on
<b>!DAGSTXBURST</b>	Set the GSM transmitter to burst mode
<b>!DAGSTXFRAME</b>	Set the GSM Tx frame structure
<b>!DALGAVGAGC</b>	Return averaged Rx AGC value (LTE)
<b>!DALGRXAGC</b>	Return Rx AGC value (LTE)



**Table C-4: Extended AT commands**

Command	Description
<b>!DALGTXAGC</b>	Return Tx AGC value and transmitter parameters (LTE)
<b>!DAOFFLINE</b>	Place modem offline
<b>!DASBAND</b>	Set the frequency band (UMTS/GSM)
<b>!DASCHAN</b>	Set the modem channel (frequency) (UMTS/GSM)
<b>!DASLNAGAIN</b>	Set the LNA (Low Noise Amplifier) gain state
<b>!DASPDM</b>	Set the PDM (Pulse Duration Modulation) value
<b>!DASTXOFF</b>	Turn off the Tx PA (Power Amplifier)
<b>!DASTXON</b>	Turn on the Tx PA (Power Amplifier)
<b>!DAWGAVGAGC</b>	Return averaged RX AGC value (WCDMA)
<b>!DAWGRXAGC</b>	Return the Rx AGC (Automatic Gain Control) value (UMTS)
<b>!DAWINFO</b>	Return WCDMA mode RF information
<b>!DAWSCONFIGRX</b>	Set the UMTS receiver to factory calibration settings
<b>!DAWSPARANGE</b>	Set the PA range state machine (UMTS)
<b>!DAWSCHAINTCM</b>	Place receive chain in test call mode (WCDMA)
<b>!DAWSSCHAIN</b>	Enable secondary receive chain (WCDMA)
<b>!DAWSTXCW</b>	Set the waveform used by the transmitter (UMTS)
<b>!DAWSTXPWR</b>	Set desired Tx power level (WCDMA)
<b>!OSDSM</b>	Display memory usage for DSM (Distributed Shared Memory) buffer pools



## >> D: Packaging

D

Sierra Wireless AirPrime Mini Cards are shipped in sealed boxes. The standard packaging (see [Figure 4-1](#)), contains a single tray with a capacity of 100 modules. (Note that some SKUs may have custom packaging—contact Sierra Wireless for SKU-specific details.)

In the standard packaging, Mini Cards are inserted, system connector first, into the bottom portion (T1) of a two-part tray. all facing the same direction. This allows the top edge of each Mini Card to contact the top of the triangular features in the top portion (T2) of the tray (see Detail A).

The top and bottom portions of the tray snap together at the four connection points.

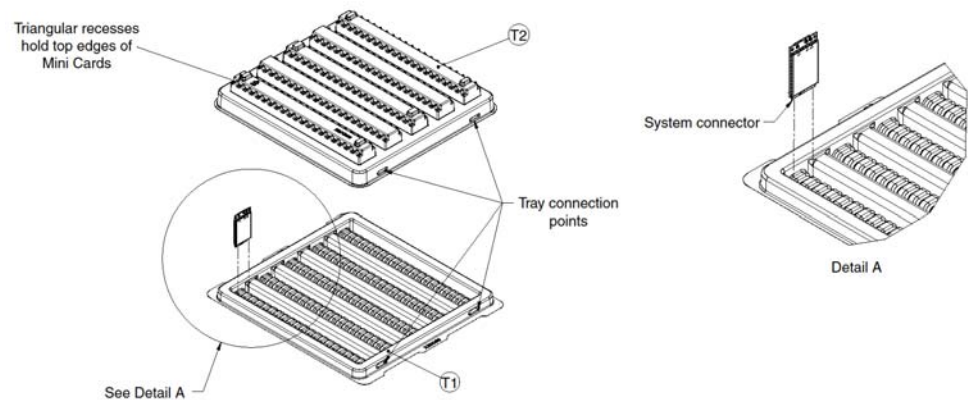


Figure 4-1: Device placement in module tray

The tray is placed in a manufacturing box (T2 at the top), sealed with a security tape (P1), and a manufacturing label is placed on the bottom-right corner, above the security tape. (See [Figure 4-2](#).)

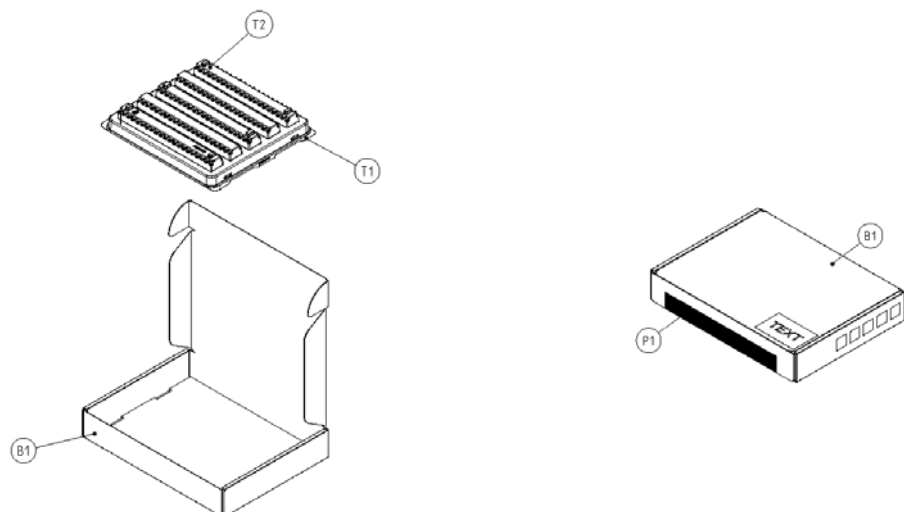


Figure 4-2: Shipping package



## E: References

## E

This guide deals specifically with hardware integration issues that are unique to AirPrime embedded modules.

### Sierra Wireless documents

The Sierra Wireless documents listed below are available from [www.sierrawireless.com](http://www.sierrawireless.com). For additional documents describing embedded module design, usage, and integration issues, contact your Sierra Wireless account representative.

### Command documents

- [1] AT Command Set for User Equipment (UE) (Release 6)  
(Doc# 3GPP TS 27.007)
- [2] AirPrime MiniCard MC73xx/MC8805 AT Command Reference  
(Doc# 4114486)

### Other Sierra documents

- [3] PCI Express Mini Card Dev Kit Quick Start Guide  
(Doc# 2130705)
- [4] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)

### Industry/other documents

The following non-Sierra Wireless references are not included in your documentation package:

- [5] FCC Regulations - Part 15 - Radio Frequency Devices
- [6] IEC-61000-4-2 level 3
- [7] IEC-61000-4-2 level (Electrostatic Discharge Immunity Test)
- [8] Mobile Station (MS) Conformance Specification; Part 4:  
Subscriber Interface Module (Doc# 3GPP TS 11.10-4)
- [9] PCI Express Mini Card Electromechanical Specification Revision  
1.2
- [10] Universal Serial Bus Specification, Rev 2.0
- [11] JESD22-A114-B
- [12] JESD22-C101



### LTE

LTE (Long Term Evolution) is a 4th-generation wireless standard. The [3GPP](#) Release 8 specification outlines the features and requirements.

Key features include.

- Peak data rate:
  - 100 Mbps DL within 20 MHz bandwidth  
(Peak DL data rate in 10 MHz bandwidth: 70 Mbps (approx.) for Cat 3 device)
  - 50 Mbps UL within 20 MHz bandwidth

Actual throughput depends on the network configuration, bandwidth assigned to the UE, the number of users, and RF signal conditions.

- Up to 200 active users in a cell (5 MHz)
- Less than 5 ms user-plane latency
- Supported bandwidths: 1.4/3/5/10/15/20 MHz (See [Table 4-2 on page 45](#) for band-specific support.)
- Spectrum flexibility: 1.4–20 MHz (3–20 MHz in future F/W release)
- Enhanced support for end-to-end [QoS](#)
- Frequency Division Duplexing (FDD)
- Physical layer uses:
  - [DL](#): OFDMA (Orthogonal Frequency Division Multiple Access).  
Modulation: QPSK, 16[QAM](#), and 64QAM
  - [UL](#): Single Carrier FDMA (single carrier modulation and orthogonal frequency multiplexing)  
Modulation: QPSK and 16QAM
- MIMO (Multi-Input Multi-Output) antenna support

### UMTS

The Universal Mobile Telecommunications System (UMTS) specification is the 3G mobile systems standard based on an evolution of GSM core network components. High-speed 3G systems implementing the UMTS standard enable improved performance for wireless data applications, delivery of enhanced multimedia content, and improved network capacity to support additional subscribers.

## HSPA

HSPA is a third generation (3G) evolution of WCDMA that combines two extensions to UMTS—HSDPA (High Speed Downlink Packet Access) and HSUPA (High Speed Uplink Packet Access).

## HSPA+

HSPA+ is an enhanced version of HSPA (High Speed Packet Access), as defined by the 3rd Generation Partnership Project (3GPP) Release 7 UMTS Specification for Mobile Terminated Equipment. Using improved modulation schemes and refined data communication protocols, HSPA+ permits increased uplink and downlink data rates.

## DC-HSPA+

Dual-Carrier HSPA+ is an enhanced version of HSPA+, as defined by the 3GPP Release 8 UMTS Specification for Mobile Terminated Equipment. DC-HSPA+ uses paired spectrum allocations to double the bandwidth available and, therefore, double downlink data rates.

## GPRS / EGPRS

GPRS and EGPRS are 2G wireless technologies providing end-to-end [packet](#) data services through reuse of existing GSM infrastructure.

GPRS / EGPRS packet data rates are determined by the number of timeslots available for downlink (Rx) and uplink (Tx), and the coding scheme used for any given transmission.

The MC7330 supports:

- GPRS—Multislot class 10 (no backoff)—Four Rx slots (maximum), two Tx slots(maximum), five active slots total

---

*Note: The network controls slot assignments based on current network loads and the bandwidth required by the mobile device - users cannot change slot assignments.*

---



- EGPRS—Multislot class 12 (with backoff. See [Table F-1 on page 97](#))—Four Rx slots (maximum), four Tx slots (maximum), five active slots total
- All standardized coding schemes (GMSK—CS 1 to CS 4, EDGE—MCS1 to MCS9)

**Table F-1: EGPRS power backoff**

Power class	Mode	Band	Coding scheme	Modulation	Power Backoff (dB)			
					1 Time slot	2 Time Slots	3 Time Slots	4 Time Slots
12	EGPRS	GSM850	MCS1–MCS4	GMSK	0	0	3.5	5.5
		GSM900						
		GSM850	MCS5–MCS9	8PSK	0	0	0	0
		GSM900						
		GSM1800	MCS1–MCS4	GMSK	0	0	2.5	3.5
		GSM1900						
		GSM1800	MCS5–MCS9	8PSK	0	0	0	0
		GSM1900						



## >> G: Acronyms

Table G-1: Acronyms and definitions

Acronym or term	Definition
<b>3GPP</b>	3rd Generation Partnership Project
<b>8PSK</b>	Octagonal Phase Shift Keying
<b>AGC</b>	Automatic Gain Control
<b>A-GPS</b>	Assisted GPS
<b>API</b>	Application Programming Interface
<b>BER</b>	Bit Error Rate—A measure of receive sensitivity
<b>BLER</b>	Block Error Rate
<b>bluetooth</b>	Wireless protocol for data exchange over short distances
<b>CDG</b>	CDMA Development Group—a consortium of companies that develop and promote the products and services for <a href="#">CDMA</a> wireless systems.
<b>CDMA</b>	Code Division Multiple Access. A wideband spread spectrum technique used in digital cellular, personal communications services, and other wireless networks. Wide channels (1.25 MHz) are obtained through spread spectrum transmissions, thus allowing many active users to share the same channel. Each user is assigned a unique digital code, which differentiates the individual conversations on the same channel.
<b>CQI</b>	Channel Quality Indication
<b>COM</b>	Communication port
<b>CS</b>	Circuit-switched
<b>CW</b>	Continuous waveform
<b>dB</b>	Decibel = $10 \times \log_{10} (P1/P2)$ <i>P1 is calculated power; P2 is reference power</i>  Decibel = $20 \times \log_{10} (V1/V2)$ <i>V1 is calculated voltage, V2 is reference voltage</i>
<b>dBm</b>	A logarithmic (base 10) measure of relative power (dB for decibels); relative to milliwatts (m). A dBm value will be 30 units (1000 times) larger (less negative) than a dBW value, because of the difference in scale (milliwatts vs. watts).
<b>DC-HSPA+</b>	Dual Carrier HSPA+
<b>DCS</b>	Digital Cellular System A cellular communication infrastructure that uses the 1.8 GHz radio spectrum.
<b>DL</b>	Downlink (network to mobile)
<b>DUN</b>	Dial-Up Networking
<b>DRX</b>	Discontinuous Reception

**Table G-1: Acronyms and definitions (Continued)**

Acronym or term	Definition
<b>DSM</b>	Distributed Shared Memory
<b>DUT</b>	Device Under Test
<b>EDGE</b>	Enhanced Data rates for GSM Evolution
<b>EIRP</b>	Effective (or Equivalent) Isotropic Radiated Power
<b>EMC</b>	Electromagnetic Compatibility
<b>EMI</b>	Electromagnetic Interference
<b>ERP</b>	Effective Radiated Power
<b>ESD</b>	Electrostatic Discharge
<b>FCC</b>	Federal Communications Commission The U.S. federal agency that is responsible for interstate and foreign communications. The FCC regulates commercial and private radio spectrum management, sets rates for communications services, determines standards for equipment, and controls broadcast licensing. Consult <a href="http://www.fcc.gov">www.fcc.gov</a> .
<b>FDMA</b>	Frequency Division Multiple Access
<b>FER</b>	Frame Error Rate—A measure of receive sensitivity.
<b>firmware</b>	Software stored in ROM or EEPROM; essential programs that remain even when the system is turned off. Firmware is easier to change than hardware but more permanent than software stored on disk.
<b>FOTA</b>	Firmware Over The Air—Technology used to download firmware upgrades directly from the service provider, over the air.
<b>FOV</b>	Field Of View
<b>FSN</b>	Factory Serial Number—A unique serial number assigned to the mini card during manufacturing.
<b>GCF</b>	Global Certification Forum
<b>GLONASS</b>	Global Navigation Satellite System—A Russian system that uses a series of 24 satellites in middle circular orbit to provide navigational data.
<b>GMSK</b>	Gaussian Minimum Shift Keying modulation
<b>GNSS</b>	Global Navigation Satellite Systems (GPS plus GLONASS)
<b>GPRS</b>	General Packet Radio Service
<b>GPS</b>	Global Positioning System An American system that uses a series of 24 satellites in middle circular orbit to provide navigational data.
<b>GSM</b>	Global System for Mobile Communications
<b>Host</b>	The device into which an embedded module is integrated
<b>HSDPA</b>	High Speed Downlink Packet Access

Table G-1: Acronyms and definitions (Continued)

Acronym or term	Definition
<b>HSPA+</b>	Enhanced HSPA, as defined in 3GPP Release 7 and beyond
<b>HSUPA</b>	High Speed Uplink Packet Access
<b>Hz</b>	Hertz = 1 cycle/second
<b>IC</b>	Industry Canada
<b>IF</b>	Intermediate Frequency
<b>IMEI</b>	International Mobile Equipment Identity
<b>IMS</b>	IP Multimedia Subsystem—Architectural framework for delivering IP multimedia services.
<b>inrush current</b>	Peak current drawn when a device is connected or powered on
<b>inter-RAT</b>	Radio Access Technology
<b>IOT</b>	Interoperability Testing
<b>IS</b>	Interim Standard. After receiving industry consensus, the TIA forwards the standard to ANSI for approval.
<b>LED</b>	Light Emitting Diode. A semiconductor diode that emits visible or infrared light.
<b>LHCP</b>	Left-Hand Circular Polarized
<b>LNA</b>	Low Noise Amplifier
<b>LPM</b>	Low Power Mode
<b>LPT</b>	Line Print Terminal
<b>LTE</b>	Long Term Evolution—a high-performance air interface for cellular mobile communication systems.
<b>MCS</b>	Modulation and Coding Scheme
<b>MHz</b>	Megahertz = 10e6 Hz
<b>MIMO</b>	Multiple Input Multiple Output—wireless antenna technology that uses multiple antennas at both transmitter and receiver side. This improves performance.
<b>NAS/AS</b>	Network Access Server
<b>NC</b>	No Connect
<b>NIC</b>	Network Interface Card
<b>NMEA</b>	National Marine Electronics Association
<b>OEM</b>	Original Equipment Manufacturer—a company that manufactures a product and sells it to a reseller.
<b>OFDMA</b>	Orthogonal Frequency Division Multiple Access

**Table G-1: Acronyms and definitions (Continued)**

Acronym or term	Definition
<b>OMA DM</b>	Open Mobile Alliance Device Management—A device management protocol.
<b>OTA</b>	‘Over the air’ (or radiated through the antenna)
<b>PA</b>	Power Amplifier
<b>packet</b>	A short, fixed-length block of data, including a header, that is transmitted as a unit in a communications network.
<b>PCB</b>	Printed Circuit Board
<b>PCS</b>	Personal Communication System A cellular communication infrastructure that uses the 1.9 GHz radio spectrum.
<b>PDN</b>	Packet Data Network
<b>PMI</b>	Pre-coding Matrix Index
<b>PSS</b>	Primary synchronisation signal
<b>PST</b>	Product Support Tools
<b>PTCRB</b>	PCS Type Certification Review Board
<b>QAM</b>	Quadrature Amplitude Modulation. This form of modulation uses amplitude, frequency, and phase to transfer data on the carrier wave.
<b>QMI</b>	Qualcomm MSM/Modem Interface
<b>QOS</b>	Quality of Service
<b>QPSK</b>	Quadrature Phase-Shift Keying
<b>QPST</b>	Qualcomm Product Support Tools
<b>RAT</b>	Radio Access Technology
<b>RF</b>	Radio Frequency
<b>RI</b>	Ring Indicator
<b>roaming</b>	A cellular subscriber is in an area where service is obtained from a cellular service provider that is not the subscriber’s provider.
<b>RSE</b>	Radiated Spurious Emissions
<b>RSSI</b>	Received Signal Strength Indication
<b>SDK</b>	Software Development Kit
<b>SED</b>	Smart Error Detection
<b>Sensitivity (Audio)</b>	Measure of lowest power signal that the receiver can measure.
<b>Sensitivity (RF)</b>	Measure of lowest power signal at the receiver input that can provide a prescribed BER/BLER/SNR value at the receiver output.

Table G-1: Acronyms and definitions (Continued)

Acronym or term	Definition
<b>SG</b>	An LTE signaling interface for SMS ("SMS over SGs")
<b>SIB</b>	System Information Block
<b>SIM</b>	Subscriber Identity Module. Also referred to as USIM or UICC.
<b>SIMO</b>	Single Input Multiple Output—smart antenna technology that uses a single antenna at the transmitter side and multiple antennas at the receiver side. This improves performance and security.
<b>SISO</b>	Single Input Single Output—antenna technology that uses a single antenna at both the transmitter side and the receiver side.
<b>SKU</b>	Stock Keeping Unit—identifies an inventory item: a unique code, consisting of numbers or letters and numbers, assigned to a product by a retailer for purposes of identification and inventory control.
<b>SMS</b>	Short Message Service. A feature that allows users of a wireless device on a wireless network to receive or transmit short electronic alphanumeric messages (up to 160 characters, depending on the service provider).
<b>S/N</b>	Signal-to-noise (ratio)
<b>SNR</b>	Signal-to-Noise Ratio
<b>SOF</b>	Start of Frame—A USB function.
<b>SSS</b>	Secondary synchronisation signal.
<b>SUPL</b>	Secure User Plane Location
<b>TIA/EIA</b>	Telecommunications Industry Association / Electronics Industry Association. A standards setting trade organization, whose members provide communications and information technology products, systems, distribution services and professional services in the United States and around the world. Consult <a href="http://www.tiaonline.org">www.tiaonline.org</a> .
<b>TIS</b>	Total Isotropic Sensitivity
<b>TRP</b>	Total Radiated Power
<b>UDK</b>	Universal Development Kit (for PCI Express Mini Cards)
<b>UE</b>	User Equipment
<b>UICC</b>	Universal Integrated Circuit Card (Also referred to as a SIM card.)
<b>UL</b>	Uplink (mobile to network)
<b>UMTS</b>	Universal Mobile Telecommunications System
<b>USB</b>	Universal Serial Bus
<b>USIM</b>	Universal Subscriber Identity Module (UMTS)
<b>VCC</b>	Supply voltage
<b>VSWR</b>	Voltage Standing Wave Ratio

**Table G-1: Acronyms and definitions (Continued)**

Acronym or term	Definition
<b>WAN</b>	Wide Area Network
<b>WCDMA</b>	Wideband Code Division Multiple Access (also referred to as UMTS)
<b>WLAN</b>	Wireless Local Area Network
<b>ZIF</b>	Zero Intermediate Frequency



# Index

## Numerics

- 3D gain, average gain
  - 3D average (GNSS), 71
- 3GPP compliance
  - GSM/GPRS/EDGE, 21
  - LTE, 21
  - UMTS, 21

## A

- acceptance tests, 75
- accessories, 19
- accuracy (GNSS), 48
- acquisition time (GNSS), 48
- acronyms and definitions, 99–104
- A-GNSS, 18
- A-GPS, 18
- antenna
  - connection considerations, 41
  - connectors, 23
  - custom, design, 42
  - diversity antenna, disabling, 42
  - GNSS, specifications, recommended, 71
  - limit, matching coaxial connections, 41
  - location, considerations, 42
  - matching, considerations, 42
  - maximum cable loss, 41
  - routing, 42
  - specification, 69–72
  - specifications, recommended, 69
  - testing, 71
- antennas
  - design checklist, 73
- API, 59
- application interface features, 16
- approvals, regulatory and industry, 67
- AT commands, 88
- averaged call mode DC power consumption, 52
- averaged standby DC power consumption, 51

## B

- bands supported, RF
  - summary, 15
  - GSM, 46
  - LTE, 45
  - WCDMA, 46
- bearers, dedicated, 18
- BER (Bit Error Rate), 45
- bit error rate (BER)
  - measure of sensitivity, 45

- block diagram
  - expanded RF, 25
  - system, 24
- bottom view, 62

## C

- cable loss
  - antenna, maximum, 41
- capacitors
  - with SIM, 33
  - with XIM\_DATA / XIM\_CLK, 33
- carrier/operator testing, 87
- cell selection, 17
- certification tests, 76
- checklist, design, 73
- communications, host to modem
  - design checklist, 74
- conducted Tx power tolerances, 47
- connection
  - grounding, 43
- connectors, 41
- connectors, required
  - host-module, 19
- control interface, 34
- CQI, 17

## D

- DC power consumption
  - averaged call mode, 52
  - averaged standby, 51
- DC-HSPA+
  - overview, 96
- desense. See RF
- design checklist
  - antennas, 73
  - component placement, 73
  - EMI/ESD, 73
  - host/modem communications, 74
  - power, 73
  - thermal, 74
- detach procedure, 18
- Development Kit contents, 19
- digital interface, 39
- dimensioned view, 63
- dimensions, 62, 63
- diversity antenna
  - disabling, 42
- diversity connector, location, 41
- drop specifications, 61

## E

### EDGE

- overview, [96](#)
- bands supported, [15](#)
- connector, required, [19](#)

### electrical specifications, [23](#)

### electrostatic discharge specifications, [62](#)

### electrostatic discharge. See ESD

### envelope correlation coefficient, [70](#)

### environmental specifications, [61–64](#)

### ESD

- design checklist, [73](#)
- protection requirements, [64](#)

### ESD specifications, [62](#)

### expanded RF block diagram, [25](#)

## F

### field of view, [71](#)

### filtering, RF desense, [44](#)

### form factor, [62](#)

### FOV, [71](#)

### free space average gain, [71](#)

### frequencies supported, [45](#)

### frequency band support

- GSM, [46](#)
- LTE, [45](#)
- WCDMA, [46](#)

## G

### gain

- GNSS, [71](#)
- maximum, [70](#)
- mean effective, [70](#)
- mean effective imbalance, [70](#)

### GERAN compliance

- GSM/GPRS/EDGE, [21](#)

### GNSS

- antenna specifications, recommended, [71](#)
- connector location, [41](#)
- features supported, [18](#)
- specifications, [48](#)

### GPRS

- overview, [96](#)
- bands supported, [15](#)

### ground specifications, [30](#)

### grounding

- connection considerations, [43](#)

### GSM

- bands supported, [15](#)
- frequency band support, [46](#)

### GSM/GPRS/EDGE

- 3GPP compliance, [21](#)
- GERAN compliance, [21](#)

## H

### host interface

- pin assignments, [25](#)

### HSDPA

- bands supported, [15](#)

### HSPA

- overview, [96](#)

### HSPA+

- overview, [96](#)
- bands supported, [15](#)

### HSUPA

- bands supported, [15](#)

### humidity specifications, [61](#)

## I

### I/O connector location, [41](#)

### I/O rise time requirements, [33](#)

### impedance

- module–antenna, [42](#)
- SIM, [33](#)

### industry approvals, [67](#)

### integration requirements, [20](#)

### interface

- control interface, [34](#)
- digital interface, [39](#)
- feature summary, [16](#)
- host, pin assignments, [25](#)
- QMI, [59](#)
- SIM, [31](#)
- software, [59](#)
- USB, [30](#)

### interference

- device generated, [44](#)
- host-generated, [43](#)
- power supply noise, [57](#)
- wireless devices, [43](#)

### Interoperability testing, [87](#)

### intra-LTE mobility, [18](#)

### IOT testing, [87](#)

### iRAT, [18](#)

### isolation, [70, 71](#)

## L

### labeling, [63](#)

### LED

- example, [36](#)

### LED output, [23, 34, 35](#)

### LTE

- 3GPP compliance, [21](#)
- overview, [95](#)
- bands supported, [15](#)
- bandwidth support, [45](#)
- features, [17](#)
- frequency band support, [45](#)

**M**

- mean effective gain, [70](#)
- mean effective gain imbalance, [70](#)
- mechanical specifications, [61–64](#)
- MIB, [17](#)
- MIMO support, [15](#)
- minicom
  - downloading and installing, [80](#)
- module
  - power states, [53–55](#)

**N**

- NAS/AS security, [17](#)
- noise
  - leakage, minimizing, [43](#)
  - RF interference, power supply, [57](#)

**O**

- OEM
  - assistance with testing, [87](#)
  - labeling, [64](#)
- operator/carrier testing, [87](#)
- ordering information, [19](#)

**P**

- packaging, [91](#)
- paging procedures, [17](#)
- PCB
  - multi-layer, shielding for RF desense, [44](#)
- PCM/I2S audion interface, [36](#)
- PDN connections, multiple, [18](#)
- pin assignments, host interface, [25](#)
- PMI, [17](#)
- polarization, [71](#)
- position location, [18](#)
- power
  - design checklist, [73](#)
  - handling, [70](#)
  - power-up timing, [55](#)
  - ramp-up timing, [55](#)
  - state machines, [54](#)
  - states, module, [53–55](#)
  - supply, RF interference, [57](#)
  - supply, ripple limit, [57](#)
  - transmit, waveform, [56](#)
- power consumption, DC
  - averaged call mode, [52](#)
  - averaged standby, [51](#)
- power specifications, [30](#)
- power tolerances, conducted Tx, [47](#)
- Product Support Tool, QUALCOMM (QPST), [59](#)
- production tests, [77](#)

- PSS, [17](#)

**Q**

- QMI interface, [59](#)
- QPST (QUALCOMM Product Support Tool), [59](#)
- QUALCOMM Product Support Tool (QPST), [59](#)
- quality assurance tests, [86](#)
- QXDM support, [59](#)

**R**

- radiated efficiency, total, [69](#)
- radiated sensitivity measurement, [44](#)
- radiation patterns, [70](#)
- references, [93](#)
- regulatory approvals, [67](#)
- regulatory information, [67–68](#)
  - limitation of liability, [67](#)
  - safety and hazards, [67](#)
- reset device, [36](#)
- resistors, external pull-up, [33](#)
- RF
  - antenna cable loss, maximum, [41](#)
  - antenna connection, considerations, [41](#)
  - connectors, required, [19](#)
  - desense
    - device-generated, [43](#)
    - harmonic energy, filtering, [44](#)
    - mitigation suggestions, [44](#)
    - shielding suggestions, [44](#)
  - interference
    - other devices, [44](#)
    - power supply, [57](#)
    - wireless devices, [43](#)
- RF bands supported
  - summary, [15](#)
  - GSM, [46](#)
  - LTE, [45](#)
  - WCDMA, [46](#)
- RF block diagram, expanded, [25](#)
- RF connector location, [41](#)
- RF specifications, [41–49](#)
- RI, [17](#)
- Rx sensitivity
  - conducted, [46, 47](#)

**S**

- sales
  - ordering, [19](#)
- SDKs available, [59](#)
- SED
  - see Smart Error Detection
- See also GPS\_DISABLE\_N, [23](#)
- See also W\_DISABLE\_N, [35](#)

- sensitivity
  - conducted, RF parameter, [46](#), [47](#)
  - defined, [45](#)
  - radiated measurement, overview, [44](#)
  - testing, overview, [44](#)
- shielding
  - module, compliance, [41](#)
  - reducing RF desense, [44](#)
- shock specifications, [61](#)
- SIB, [17](#)
- signals, [34](#)
  - SYSTEM\_RESET\_N, [36](#)
  - W\_DISABLE\_N, [35](#)
  - WAKE\_N, [34](#)
  - WLAN\_LED\_N, [35](#)
- SIM
  - capacitor recommendations, [33](#)
  - card contacts, [32](#)
  - clock rate, [33](#)
  - connector, required, [19](#)
  - electrical specifications, [33](#)
  - impedance, connectors, [33](#)
  - interface, [31](#)
  - interface diagram, [32](#)
  - operation, [33](#)
- Smart Error Detection
  - detecting module reset, [57](#)
- SMS features, [18](#)
- Snow 3G/AES security, [17](#)
- software interface, [59](#)
- specifications
  - electrical, [23](#)
  - environmental specifications, [61–64](#)
  - GNSS, [48](#)
  - mechanical, [61–64](#)
  - RF, [41–49](#)
- SSS, [17](#)
- standalone mode, concurrent, GNSS, [18](#)
- standby DC power consumption, averaged, [51](#)
- state machines, [54](#)
- support
  - features, [18](#)
  - testing assistance by Sierra Wireless, [87](#)
  - tools, [59](#)
- system acquisition, [17](#)
- system block diagram, [24](#)
- SYSTEM\_RESET\_N, [36](#)

## T

- temperature specifications, [61](#)
- temperature, module. See thermal

- testing
  - overview, [75](#)
  - acceptance tests, [75](#)
  - assistance provided by Sierra Wireless, [87](#)
  - certification tests, [76](#)
  - equipment, suggested, [87](#)
  - interoperability and operator/carrier testing, [87](#)
  - manual functional test, suggested, [77](#)
  - production tests, [77](#)
  - quality assurance tests, [86](#)
  - RF receive path, LTE, [84](#)
  - suggestions, [75–89](#)
- thermal
  - considerations, [64–65](#)
  - design checklist, [74](#)
  - dissipation, factors affecting, [64](#)
  - dissipation, suggestions, [65](#)
  - internal temperature, maximum, [65](#)
  - testing, module, [65](#)
- timing
  - power ramp-up, [55](#)
  - power-up, [55](#)
- top view, [62](#)
- transmit power waveform, [56](#)
- Tx power tolerances, conducted, [47](#)

## U

- UDK, [19](#)
- UMTS
  - 3GPP compliance, [21](#)
  - overview, [95](#)
  - bands supported, [15](#)
- Universal Development Kit, [19](#)
- USB
  - drivers, user-developed, [31](#)
  - high / full speed throughput performance, [31](#)
  - interface, [30](#)

## V

- vibration specifications, [61](#)
- VSWR, [69](#), [71](#)

## W

- W\_DISABLE\_N, [34](#), [35](#)
- WAKE\_N, [23](#), [34](#)
- warranty, [18](#)
- WCDMA
  - frequency band support, [46](#)
- Wireless Disable, [23](#), [34](#)
- Wireless Disable (GNSS), [23](#)
- Wireless Disable (Main RF), [35](#)
- WLAN\_LED\_N, [34](#), [35](#)

**Z**

ZIF (Zero Intermediate Frequency), [43](#)



**SIERRA**  
WIRELESS®